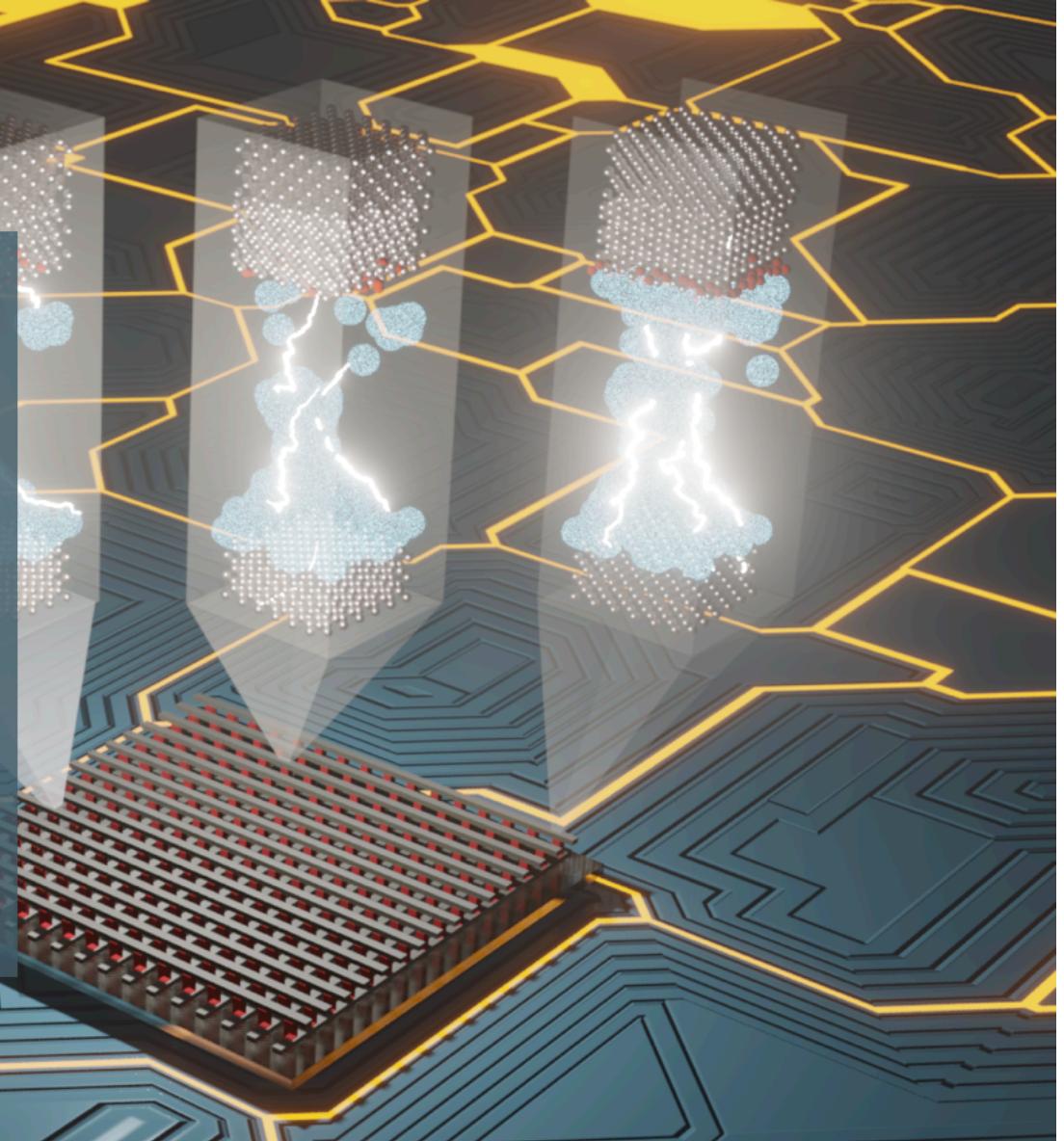


Atomistic insights behind multi-level conductance transitions in HfO_x memristors

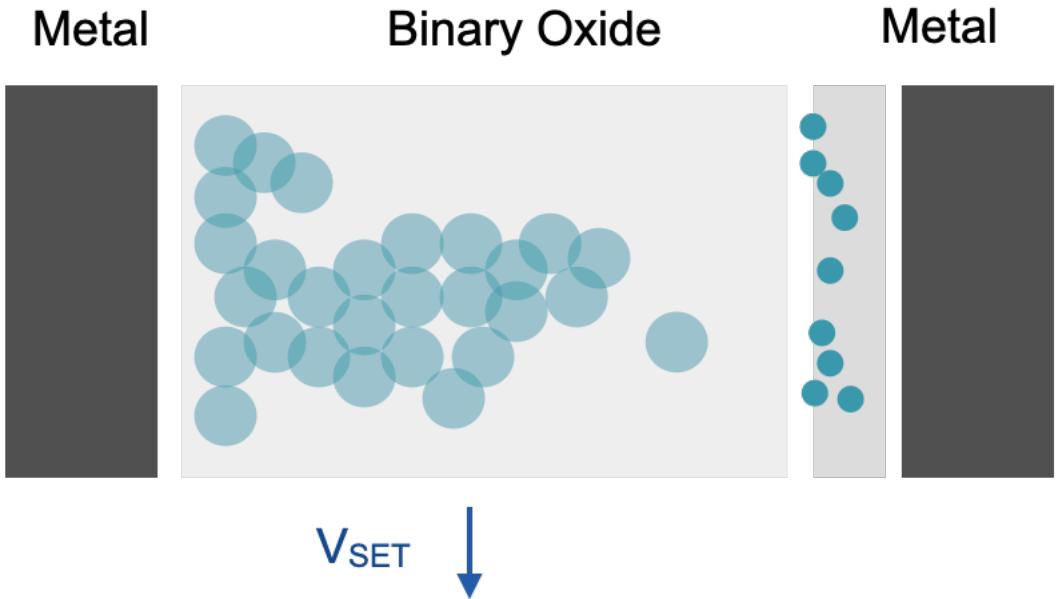
Manasa Kaniselvan

PhD Candidate, Institute for Integrated Systems
Computational Nanoelectronics Group

Coauthors: Marko Mladenovic, Jente
Clarysse, Kevin Portner, Mathieu Luisier

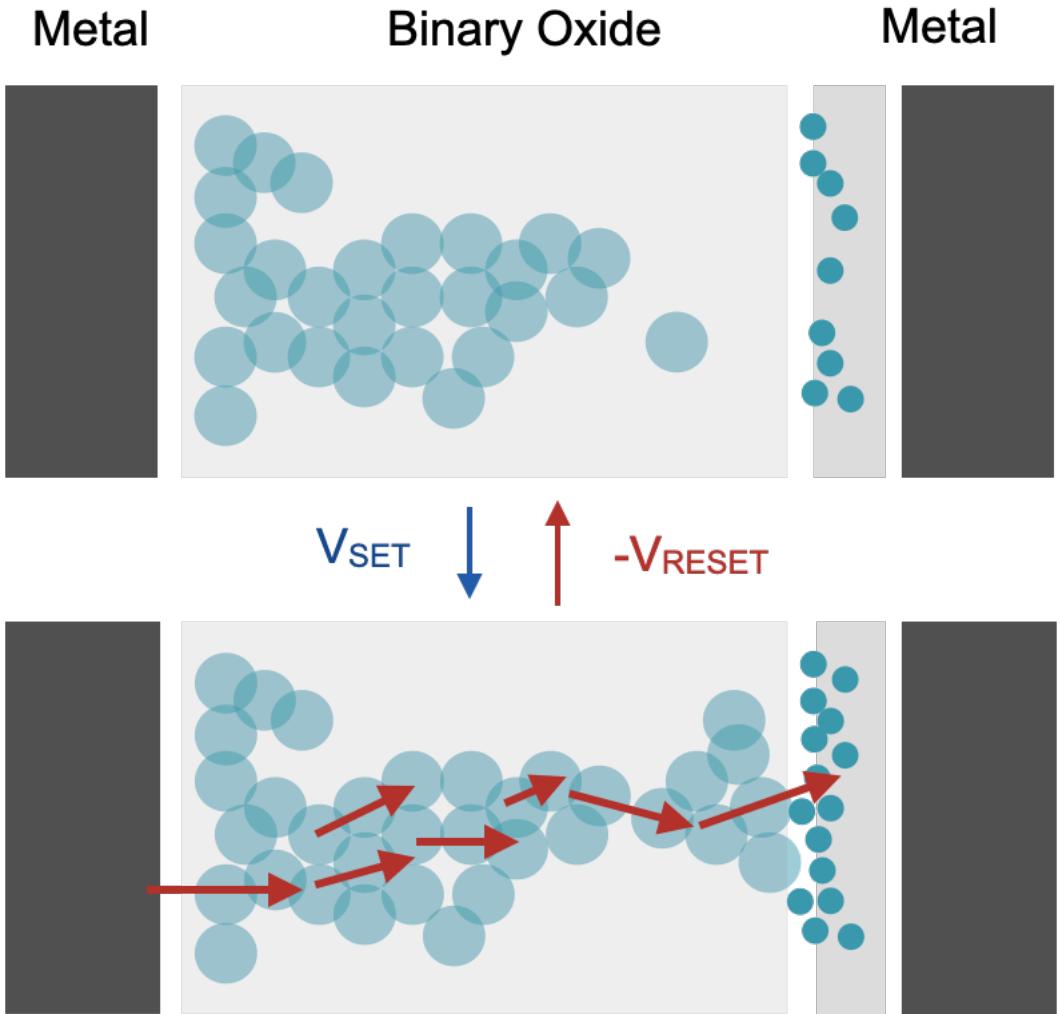


Oxide-based RRAM



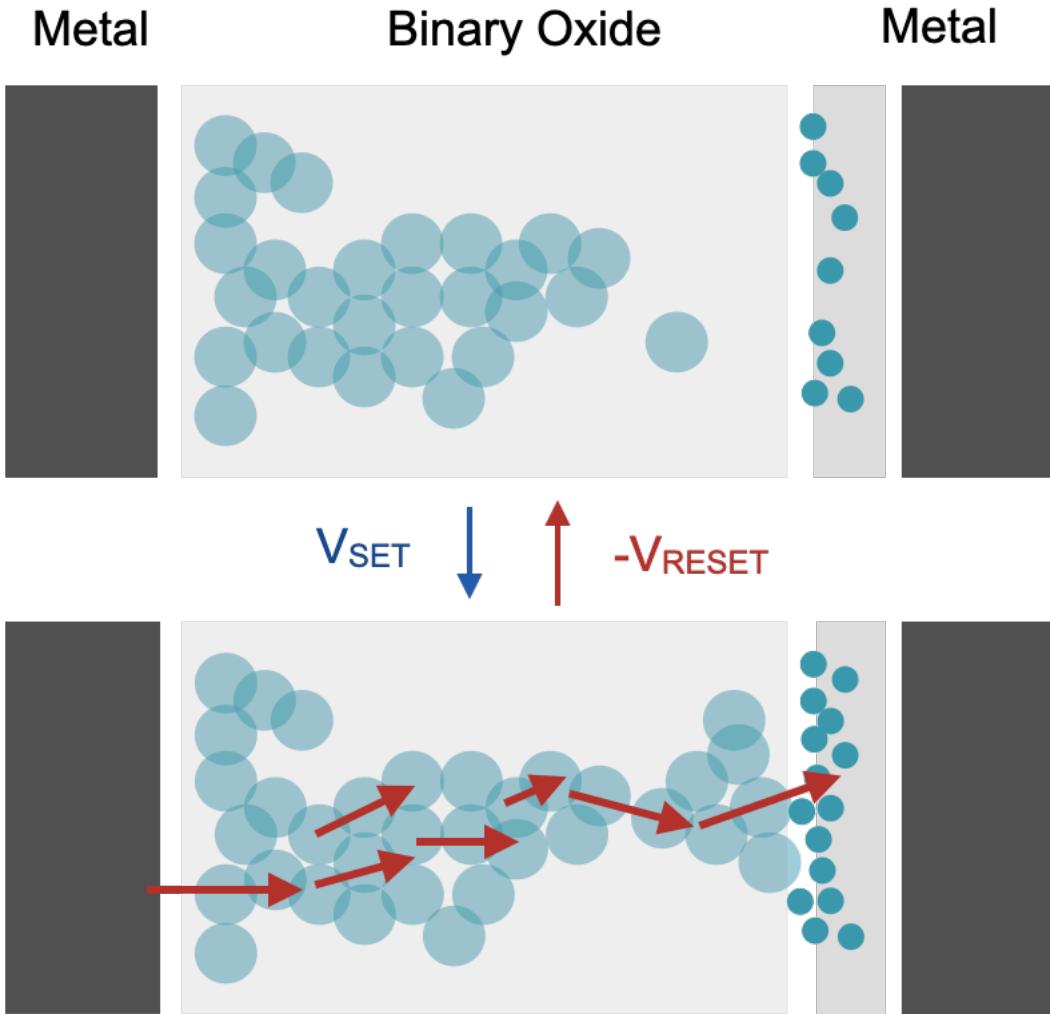
- Oxygen vacancies
- Oxygen ions

Oxide-based RRAM



→ Electronic current ● Oxygen vacancies
● Oxygen ions

Oxide-based RRAM



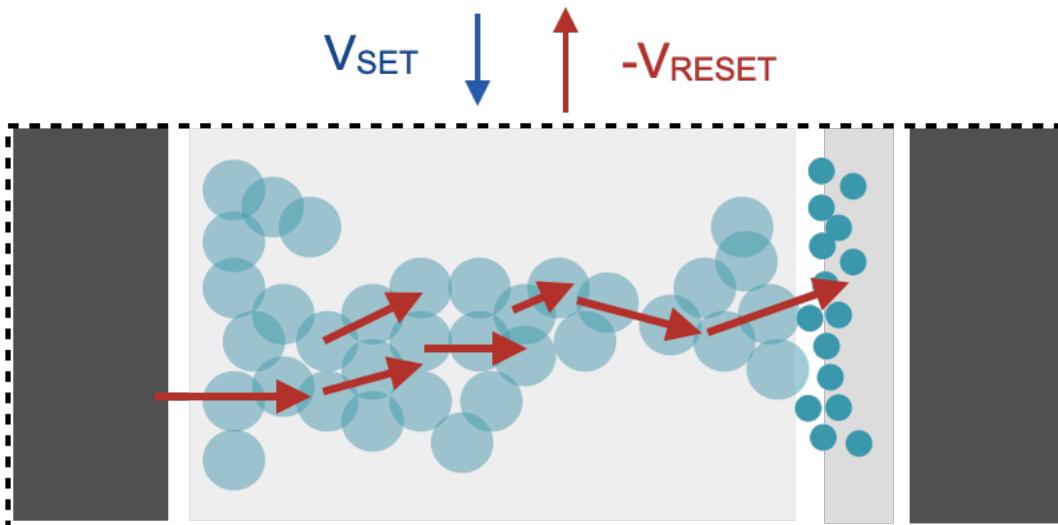
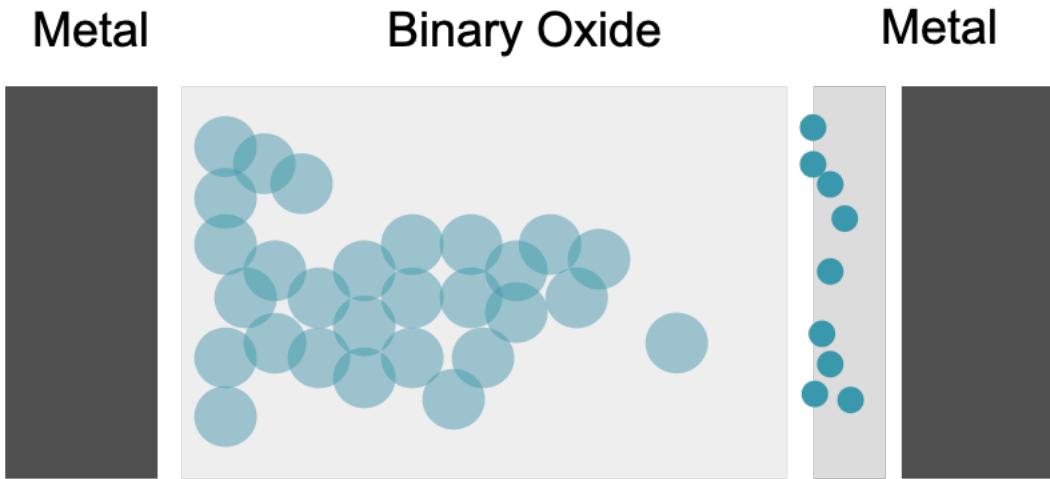
→ Electronic current

● Oxygen vacancies
● Oxygen ions

Emerging applications of these devices

- Storage, on-chip memory (digital)
- Synaptic weights (analog)

Oxide-based RRAM



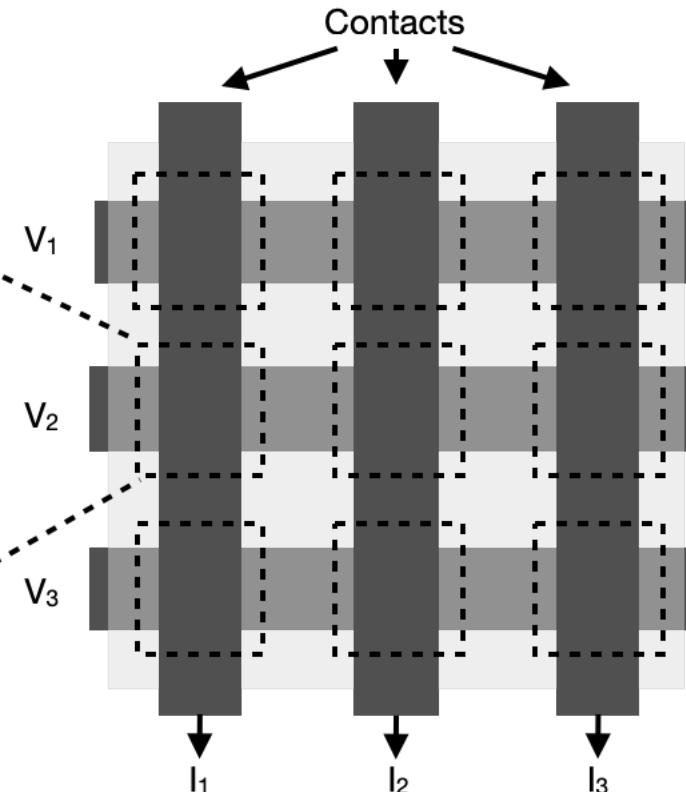
→ Electronic current

● Oxygen vacancies
● Oxygen ions

ETH zürich

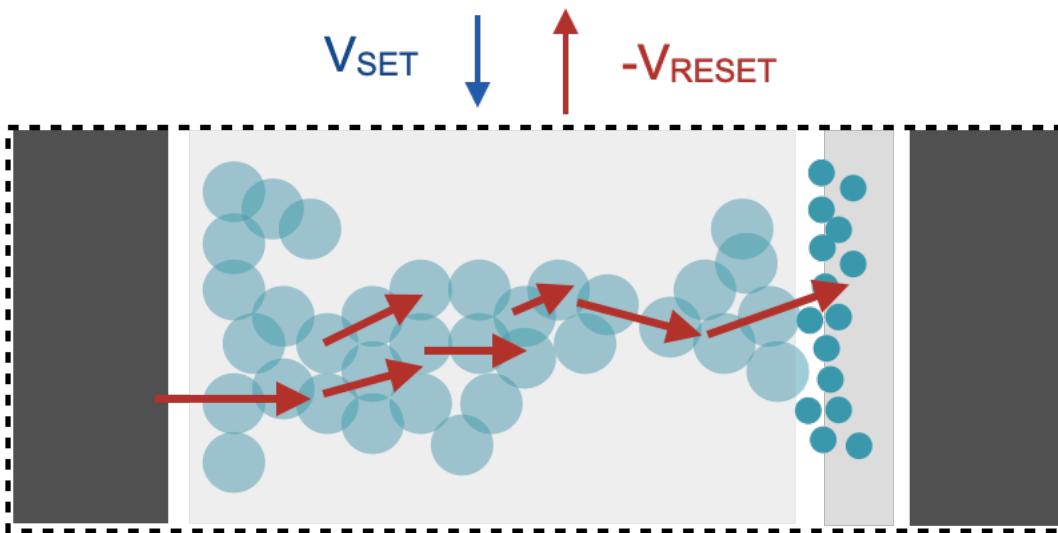
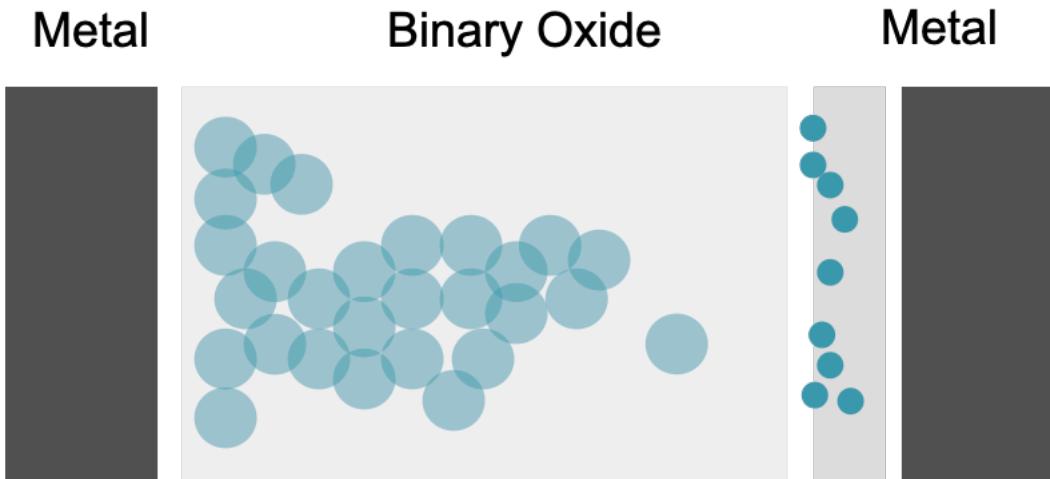
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$$I_i = \sum_{j=1}^N \frac{V_j}{R_{ji}}$$

Oxide-based RRAM

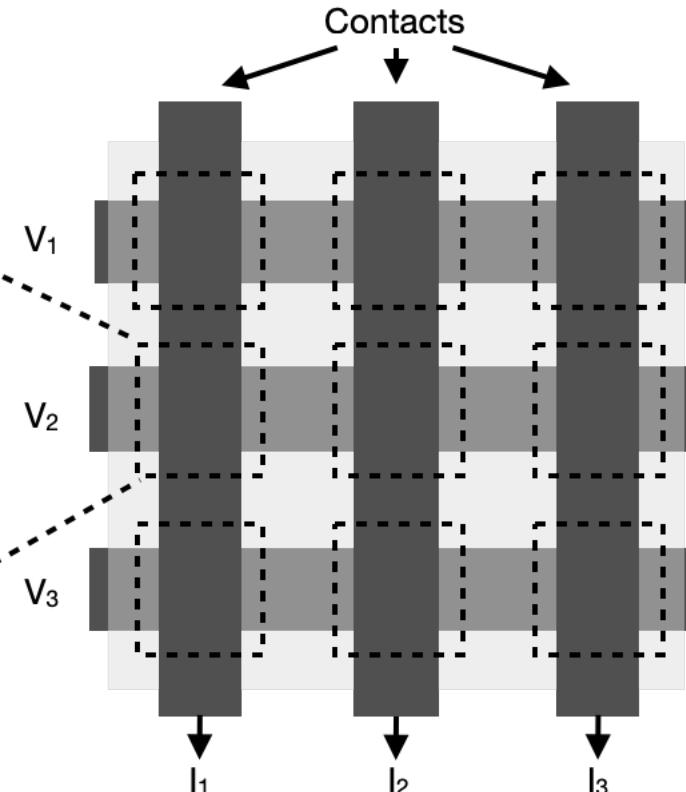


→ Electronic current

- Oxygen vacancies
- Oxygen ions

Emerging applications of these devices

- Storage, on-chip memory (digital)
- Synaptic weights (analog)

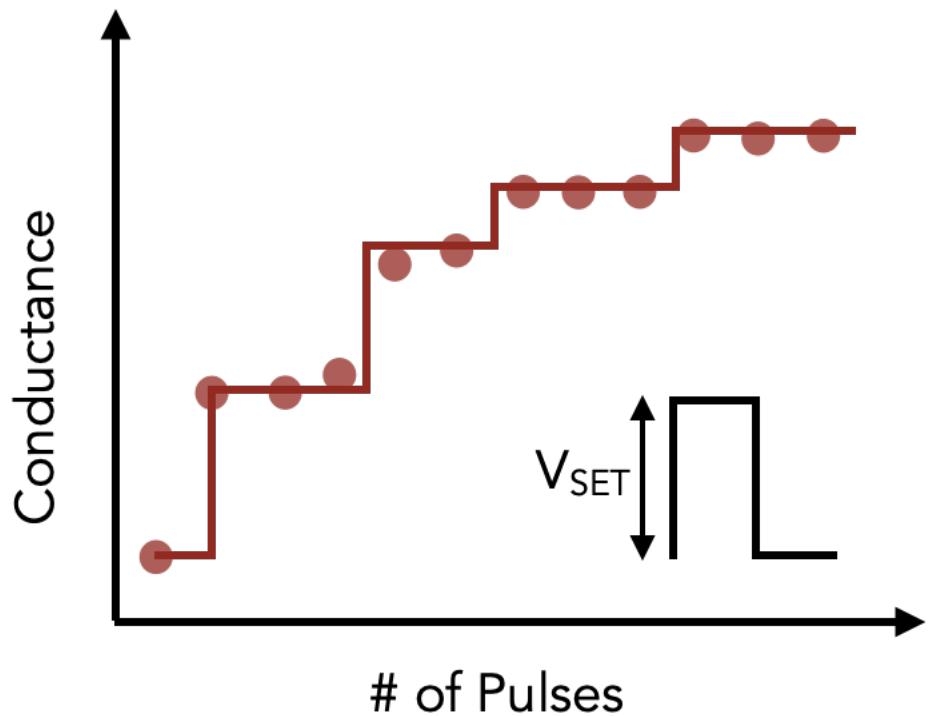


$$I_i = \sum_{j=1}^N \frac{V_j}{R_{ji}}$$

Tunable

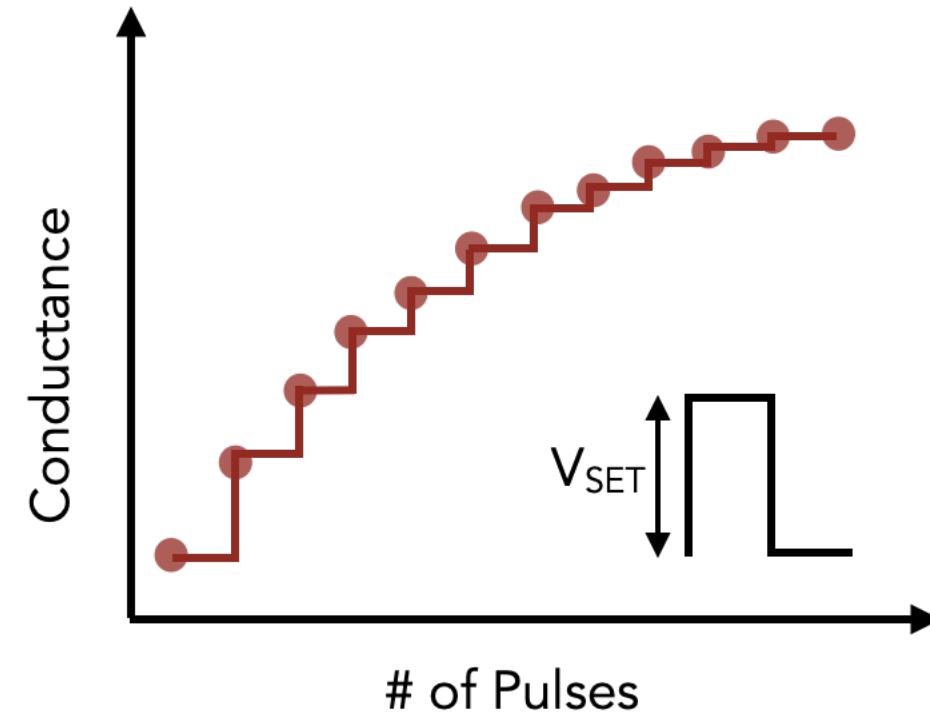
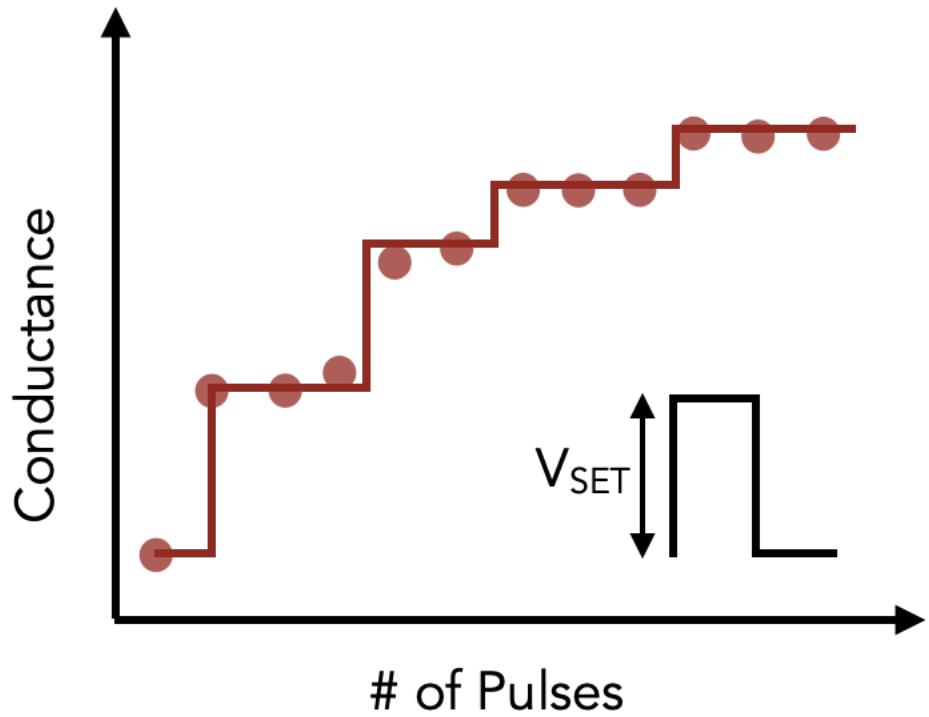
Challenges behind Designing Analog RRAM

- Increase the number of achievable conductances/synaptic weights



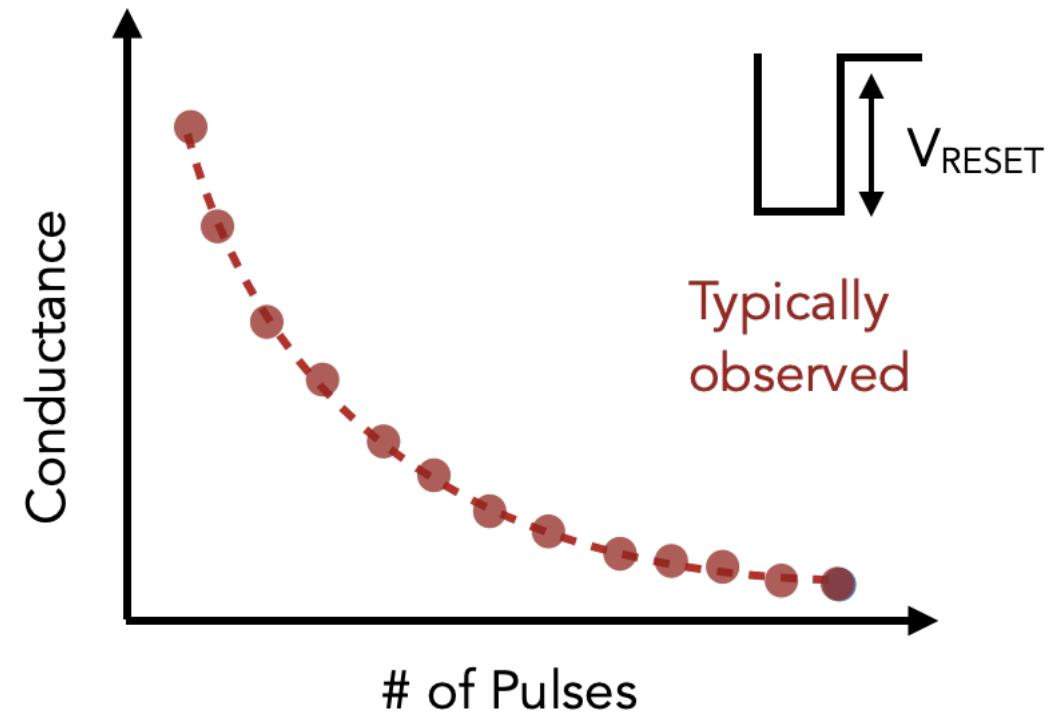
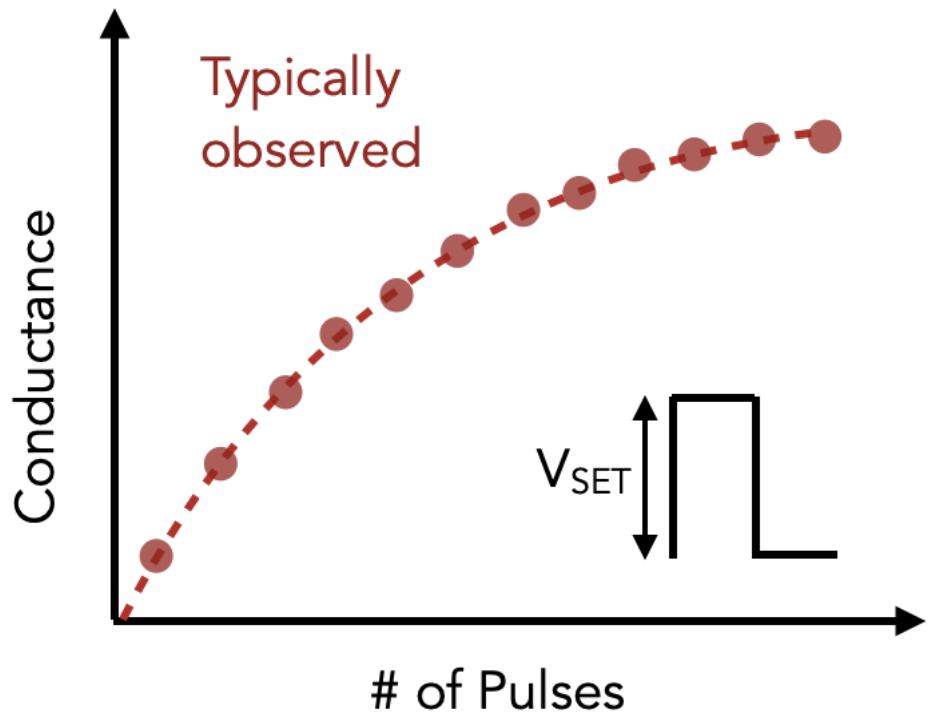
Challenges behind Designing Analog RRAM

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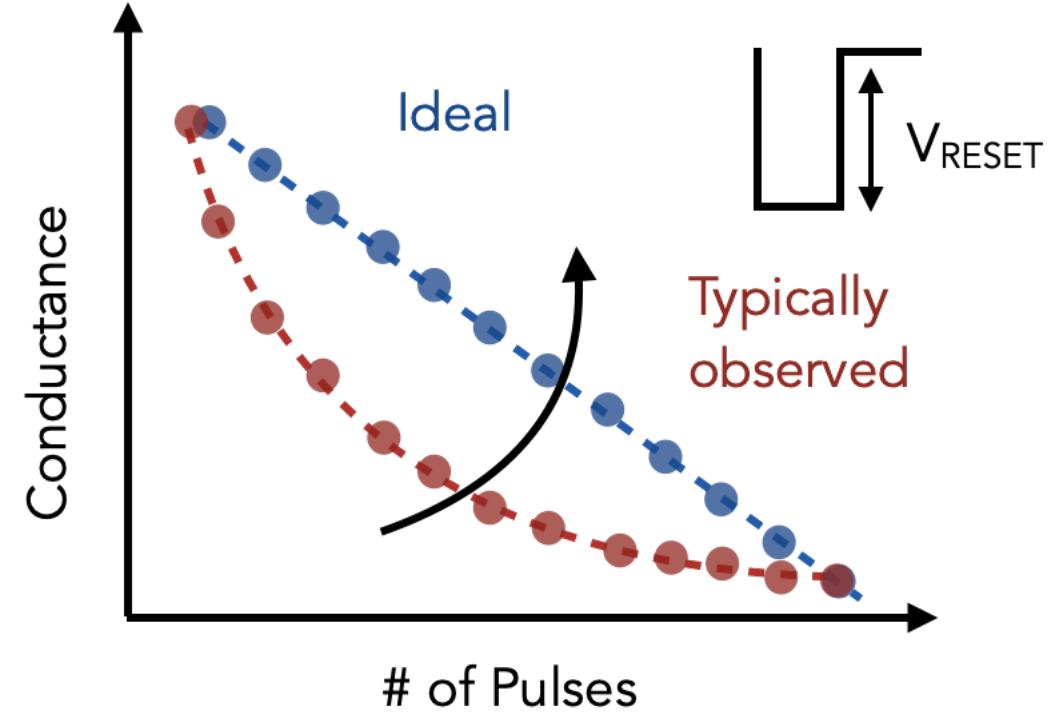
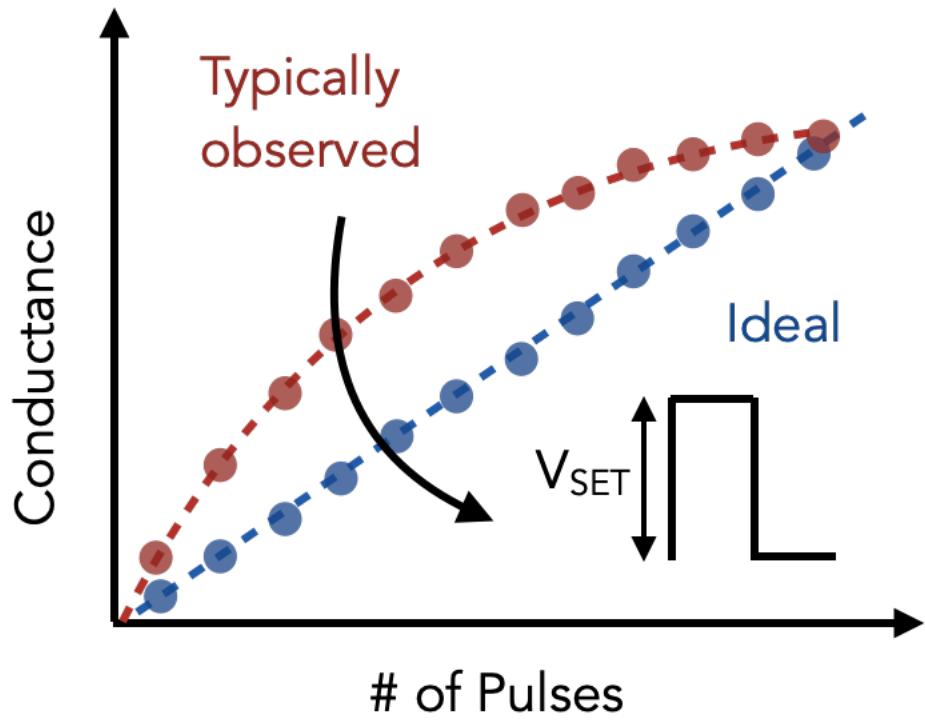
Challenges behind Designing Analog RRAM

- Increase the number of achievable conductances/synaptic weights
- Linearize the transitions between these conductances/weights

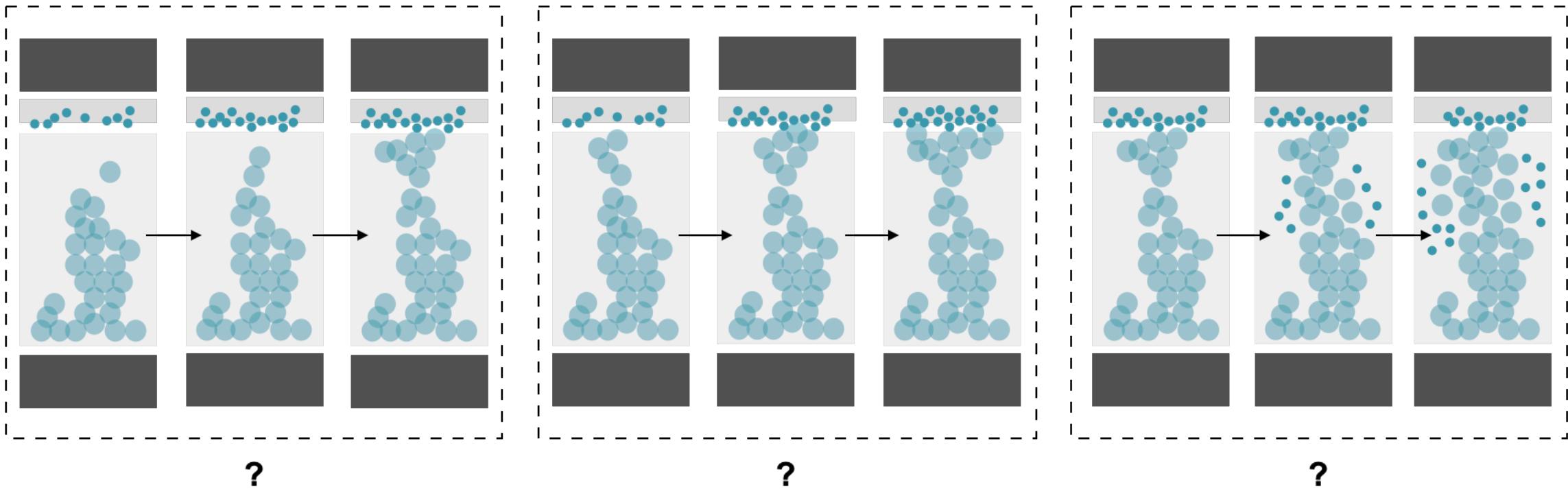


Challenges behind Designing Analog RRAM

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- Linearize the transitions between these conductances/weights



Switching Mechanisms for Intermediate States

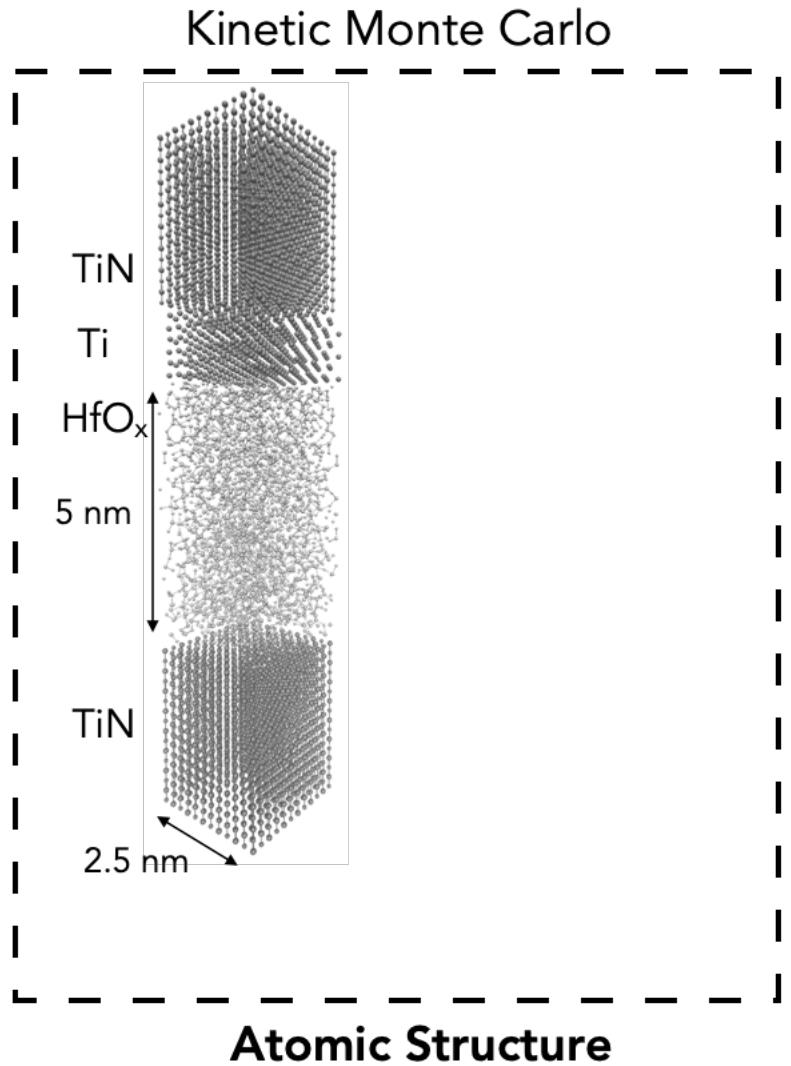


- Oxygen vacancies
- Oxygen ions

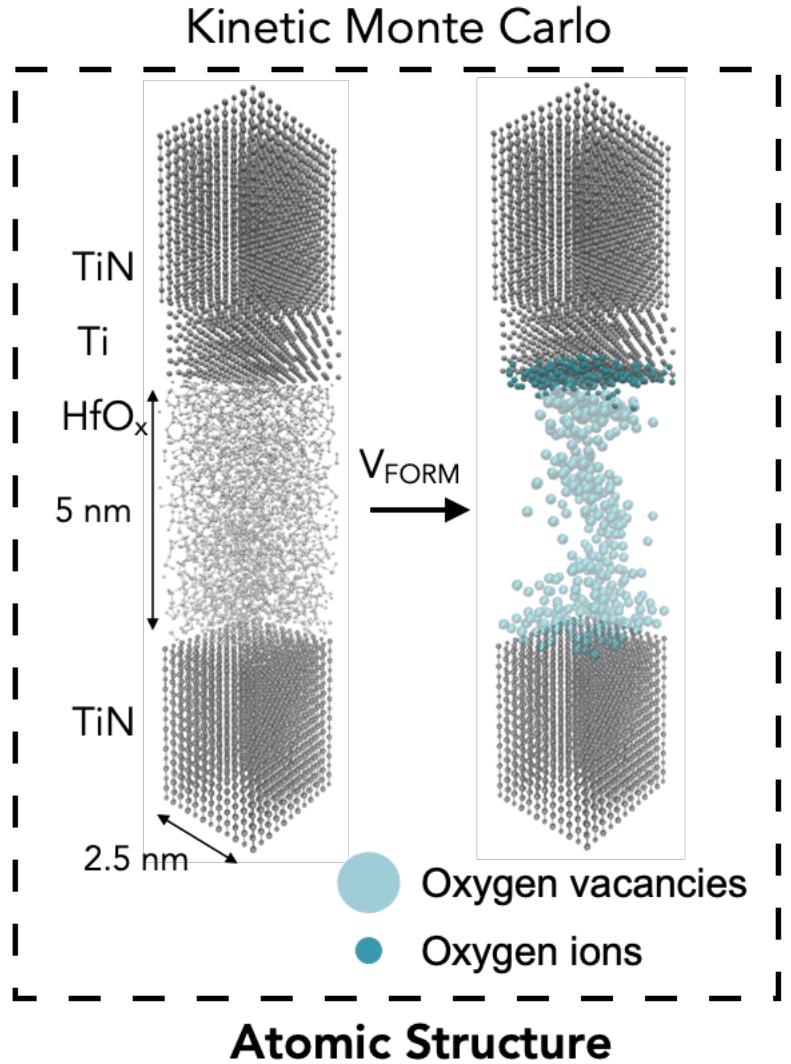
- Investigate the **ionic kinetics** and **electronic current flow** behind analog device behaviour with **ab-initio** and **atomistic simulations**

- Investigate the **ionic kinetics** and **electronic current flow** behind analog device behaviour with **ab-initio** and **atomistic simulations**
- Provide **insight** towards device design

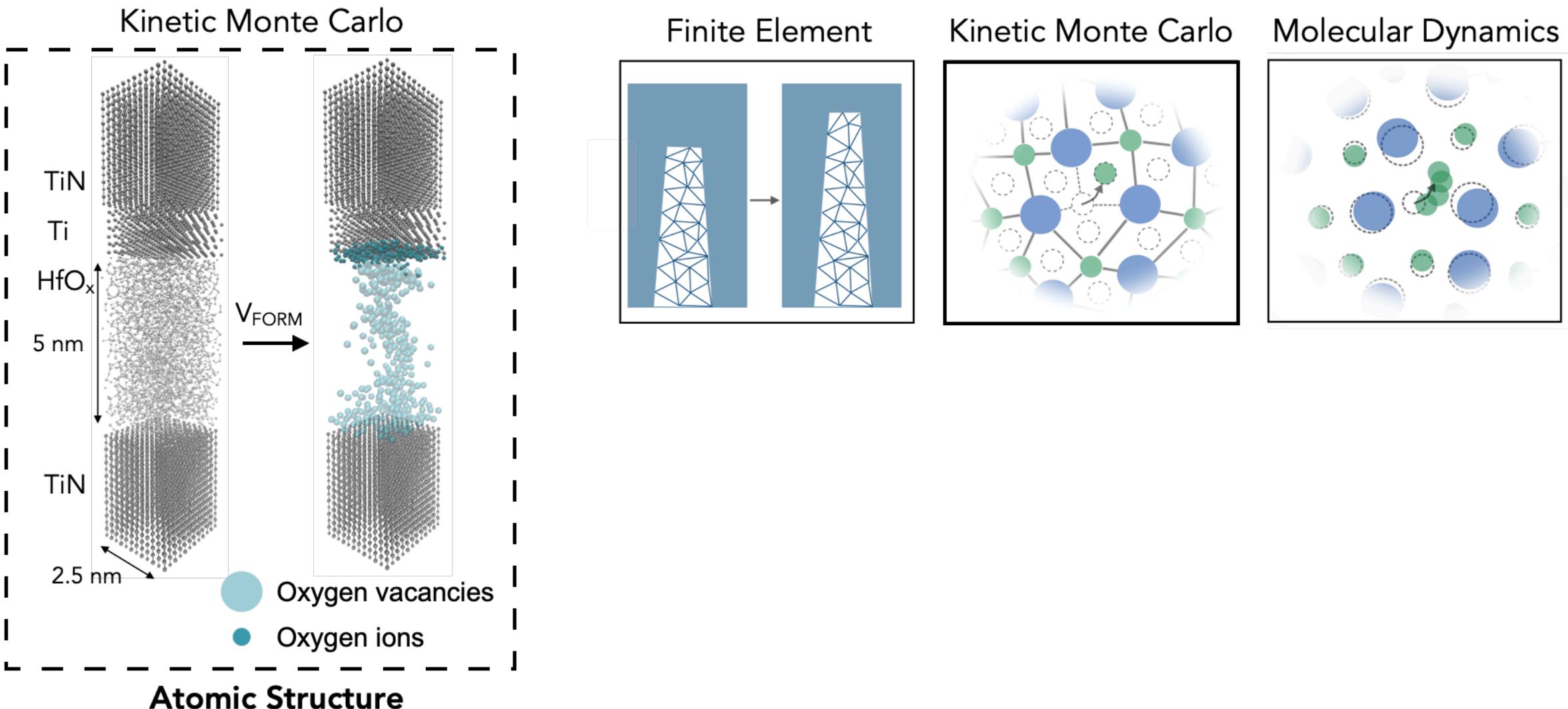
Simulation approach



Simulation approach



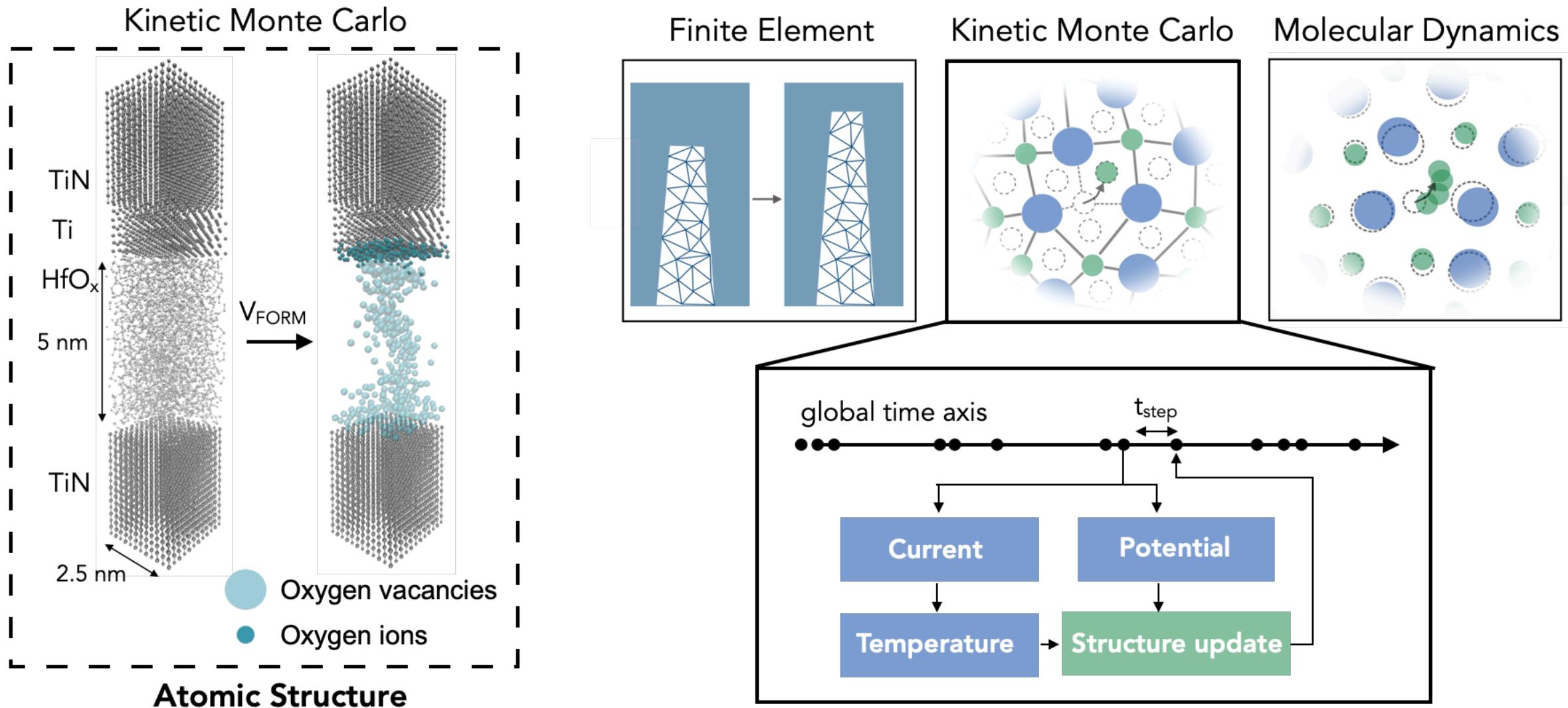
Simulation approach



Kaniselvan, M*; Maeder, A*; Mladenović, M; Luisier, M; Ziogas, A.N; "Accelerated Kinetic Monte Carlo Simulations of Atomistically-Resolved Resistive Memory Arrays". (Accepted paper) International Conference on High Performance Computing, Networking, Storage and Analysis (SC24) 2024

Kaniselvan, M.; Luisier, M.; Mladenović, M; "An Atomistic Model of Field-Induced Resistive Switching in Valence Change Memory" ACS Nano 2023

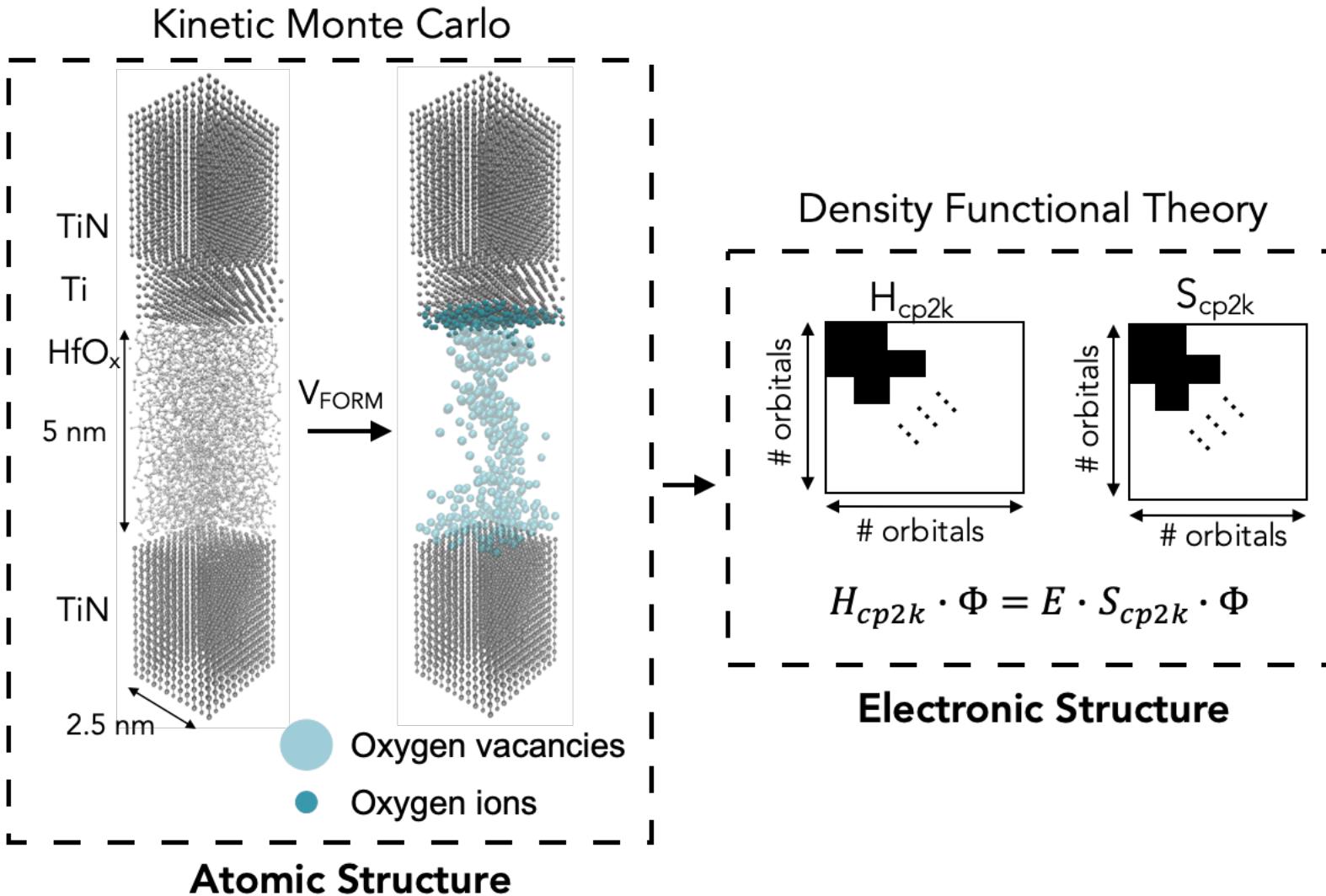
Simulation approach



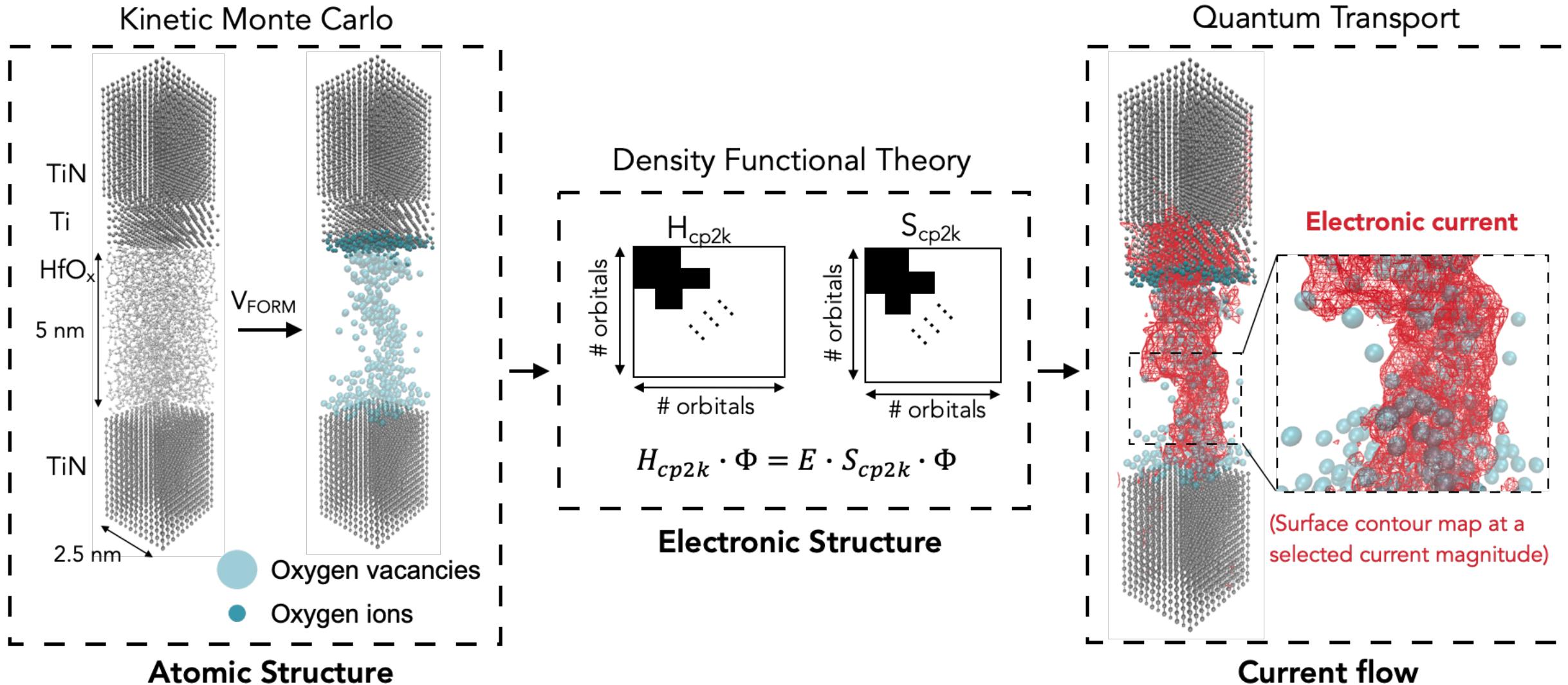
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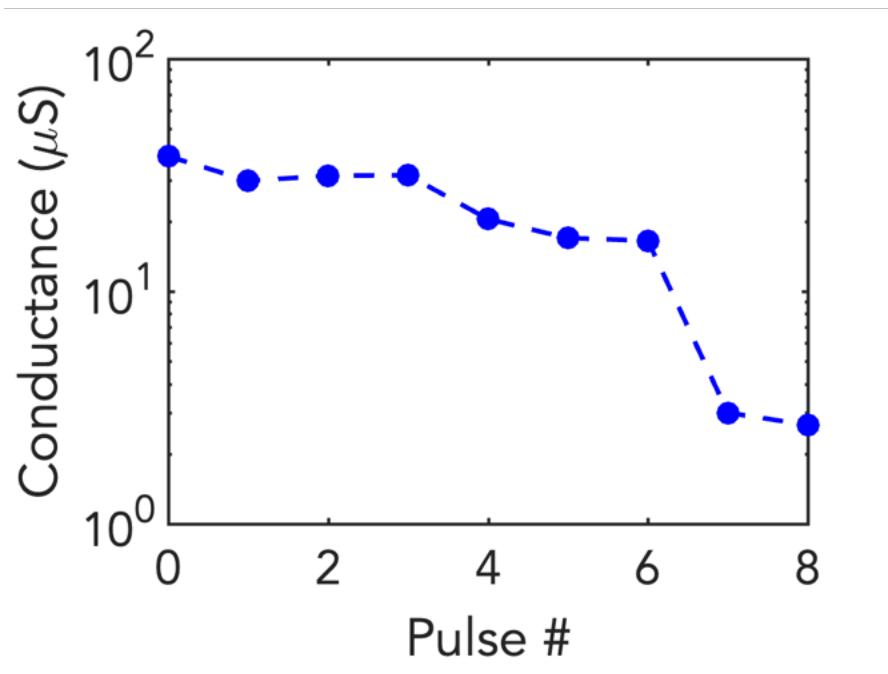
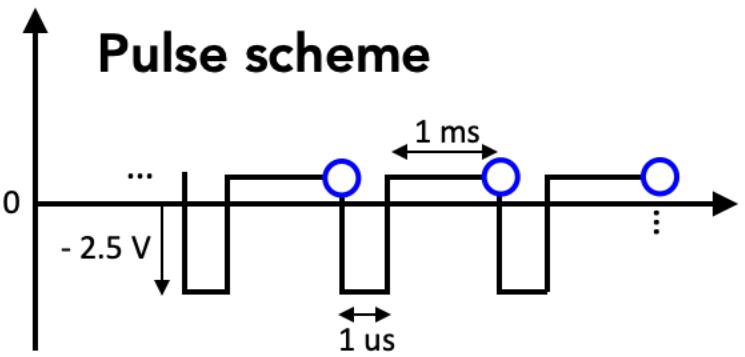
Simulation approach



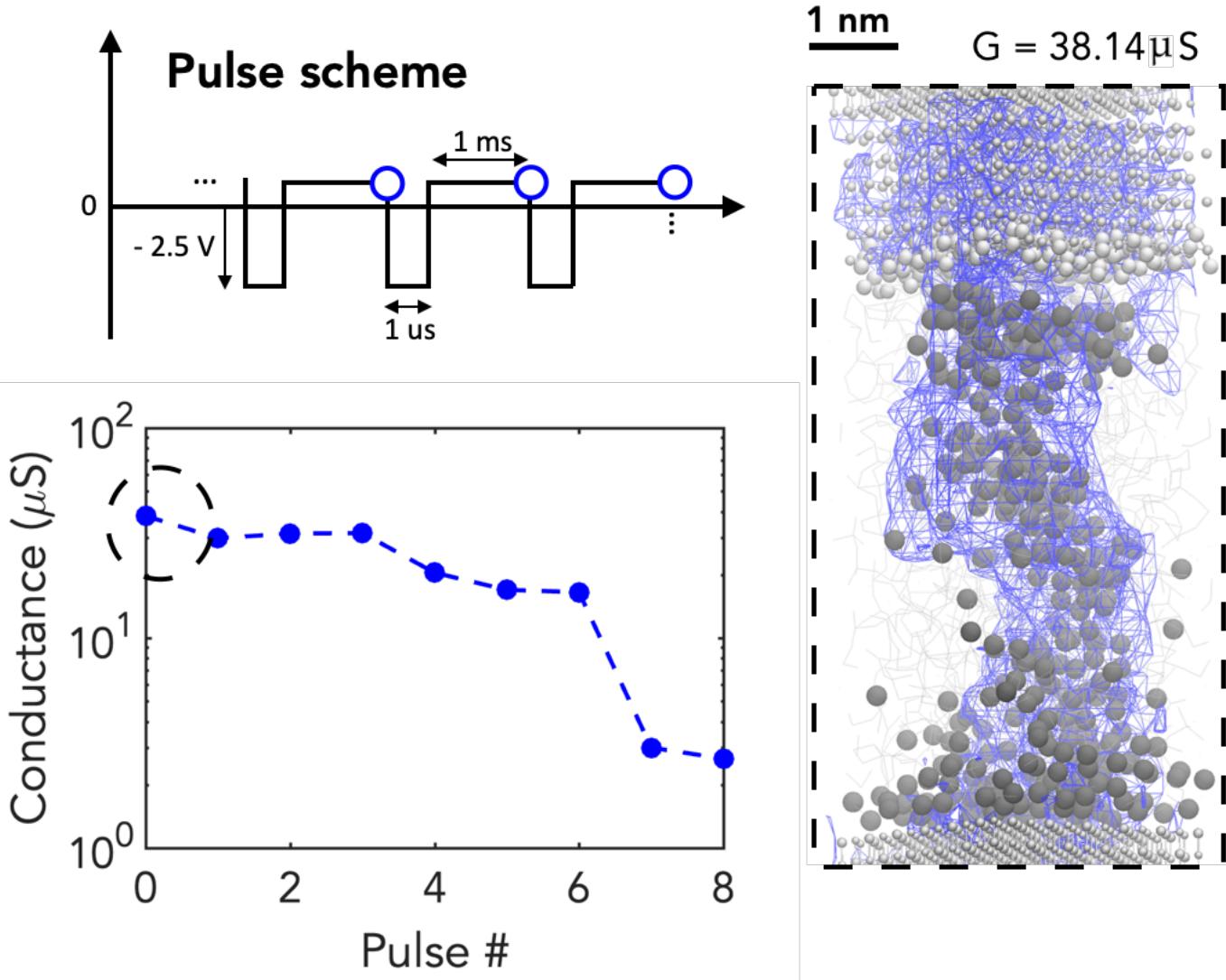
Simulation approach



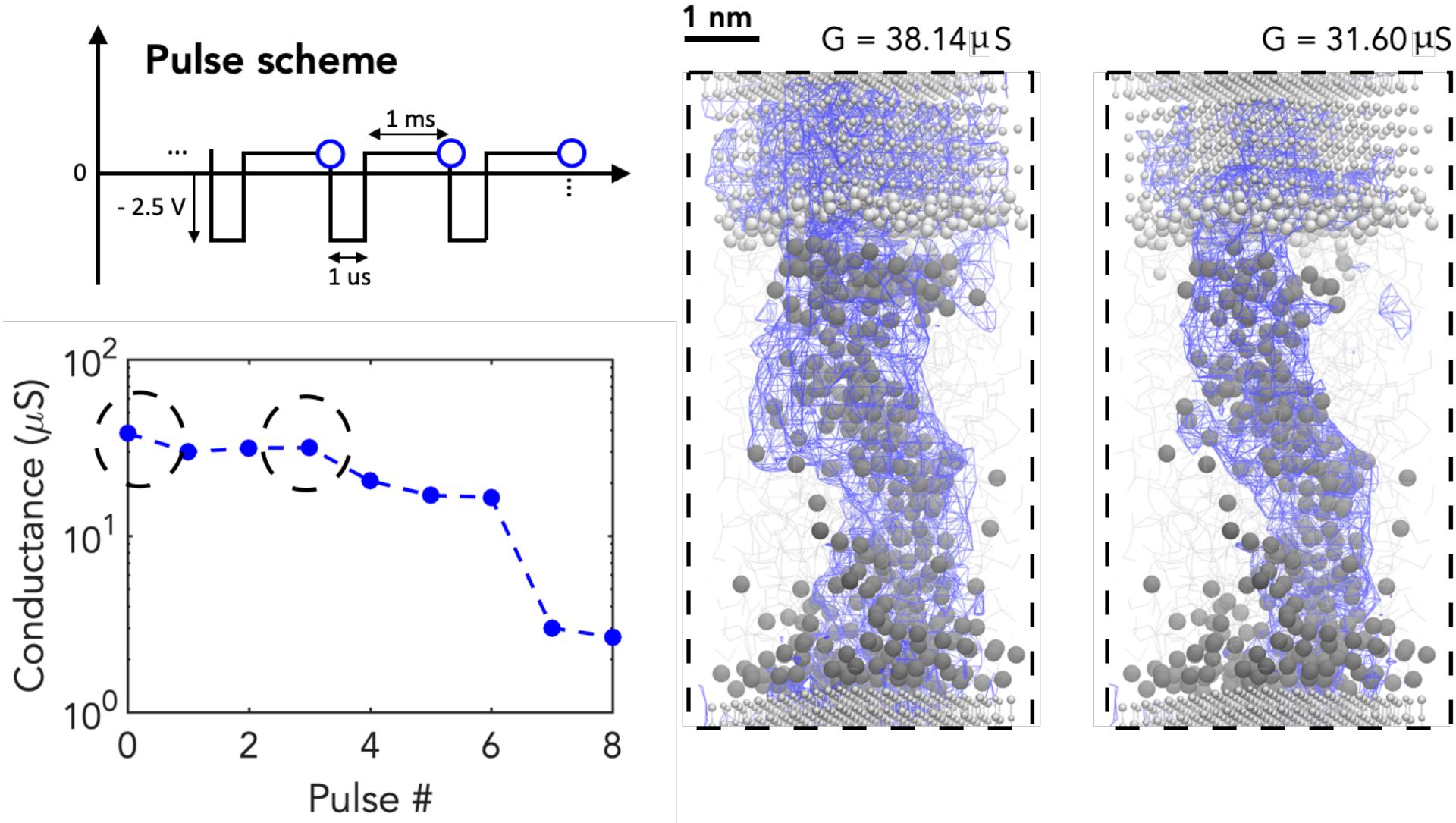
Gradual Conductance Decreases



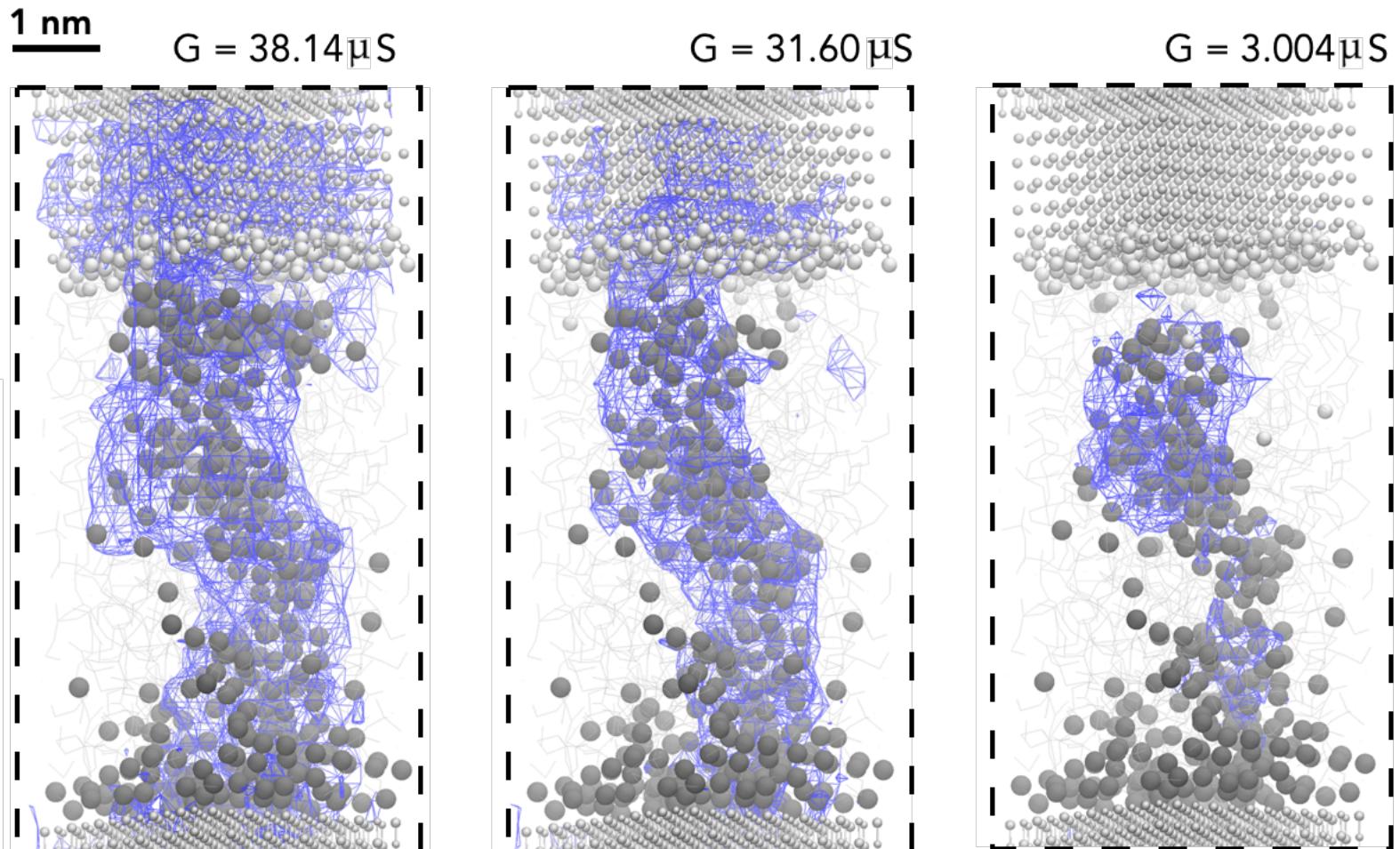
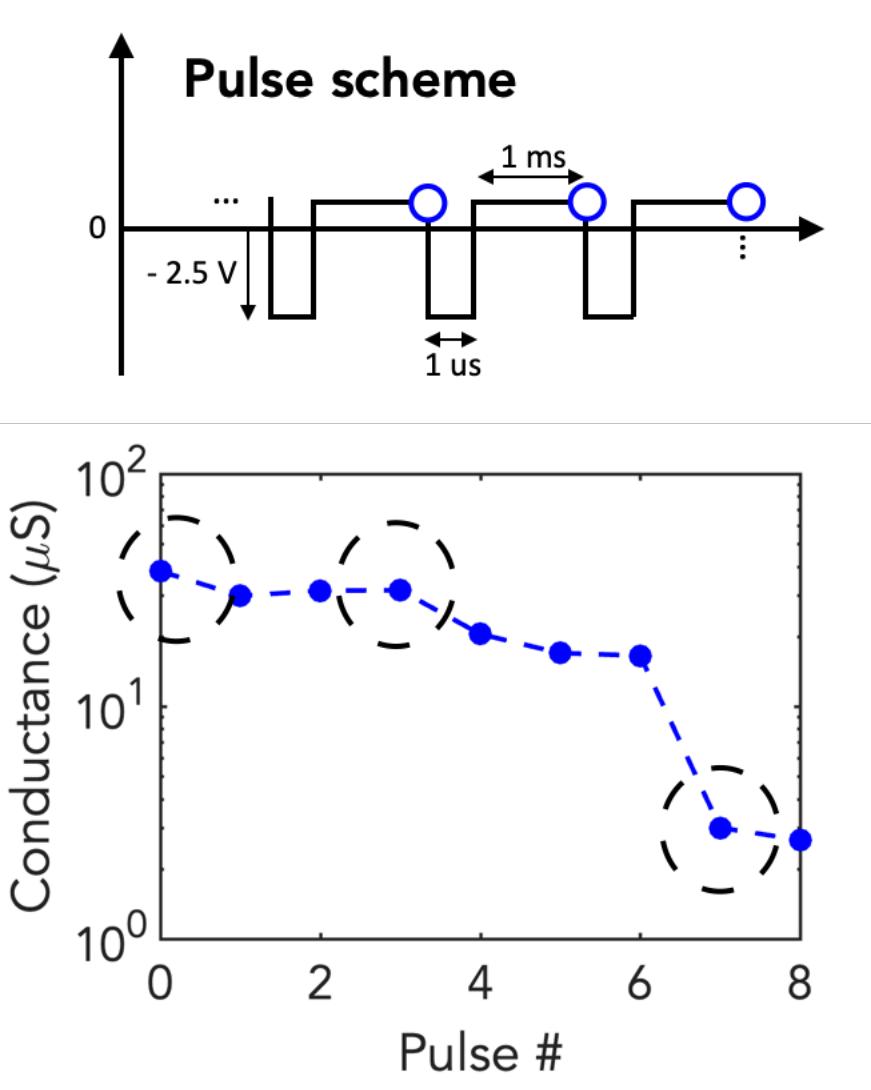
Gradual Conductance Decreases



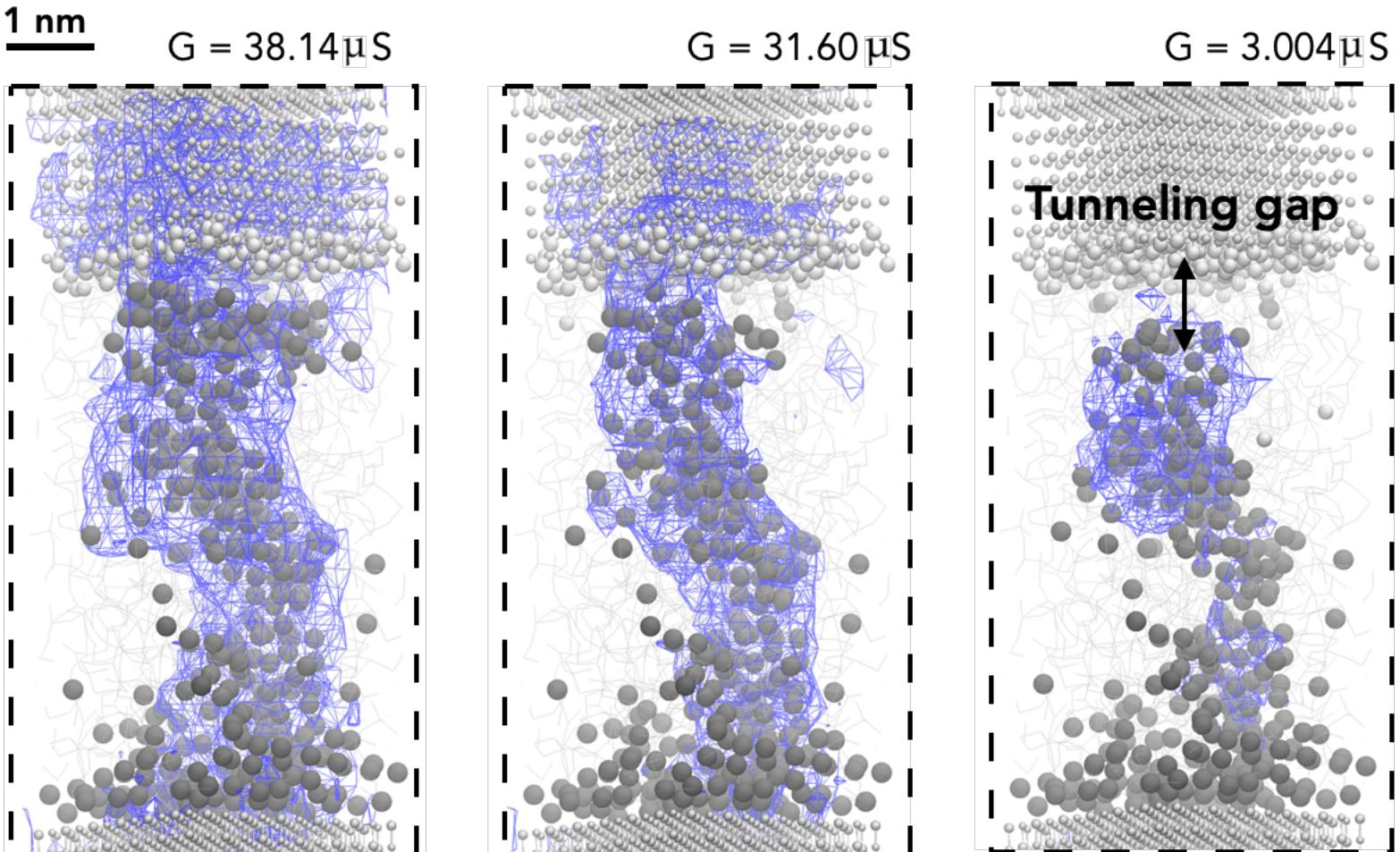
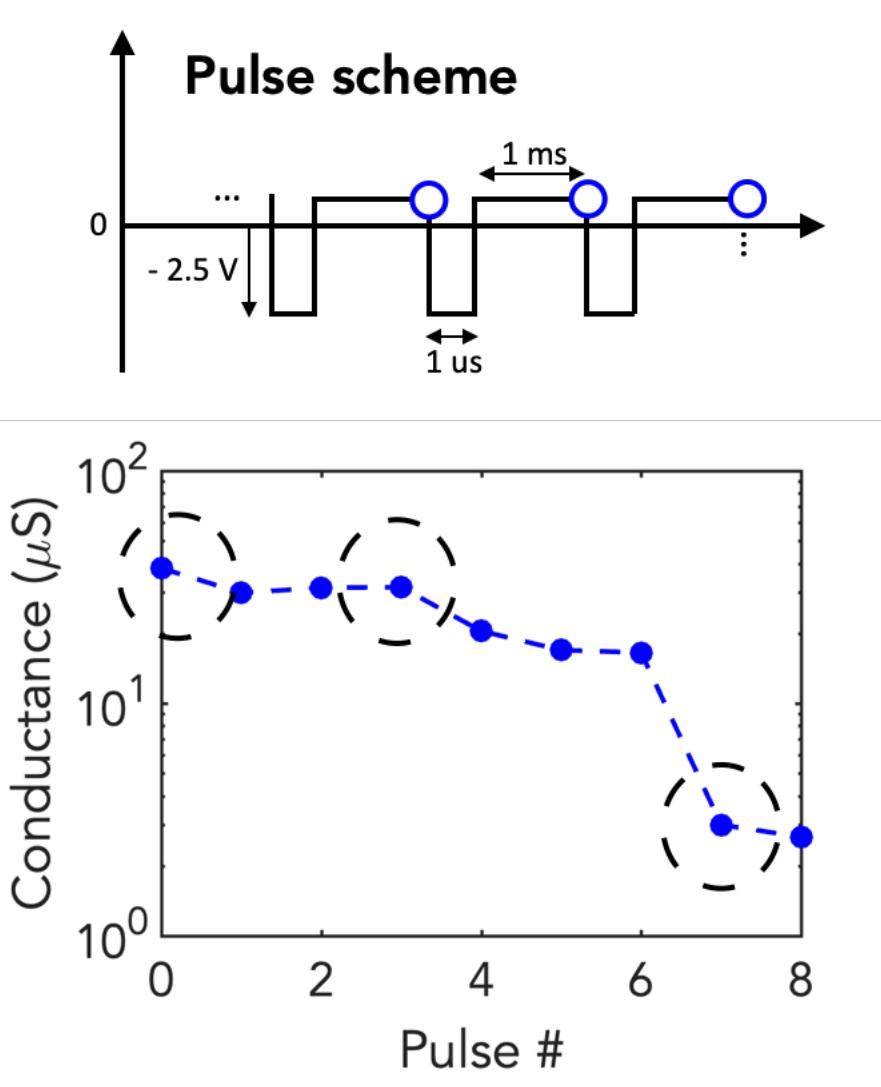
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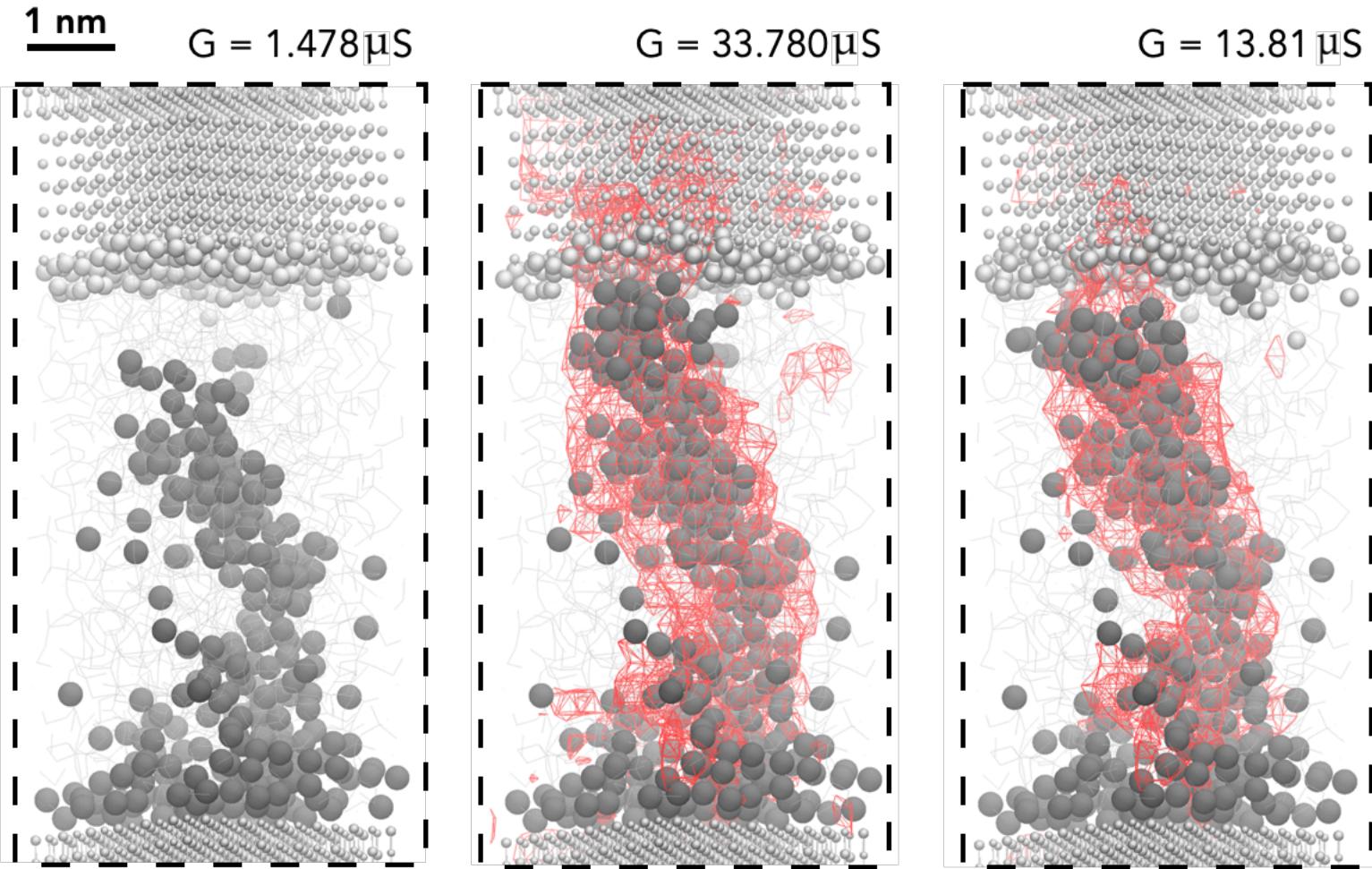
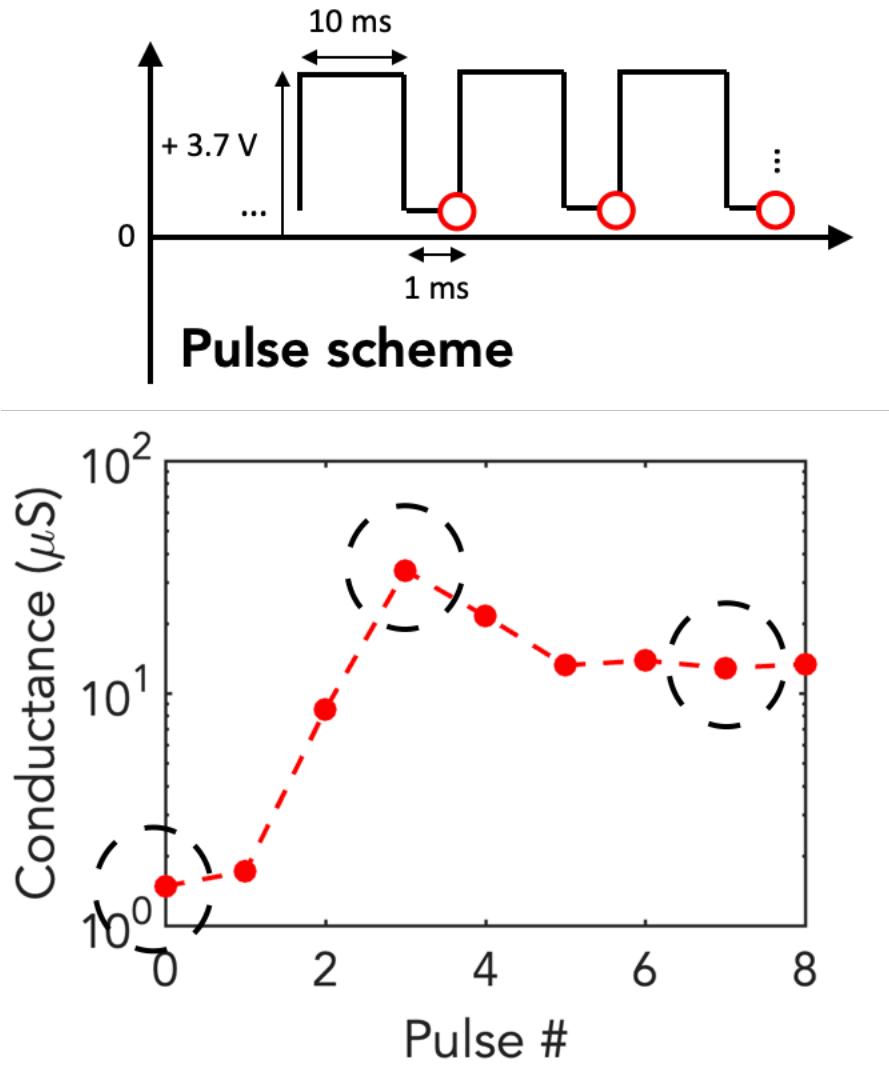
Gradual Conductance Decreases



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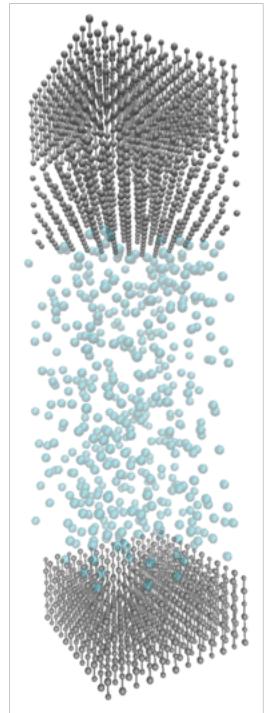


Gradual Conductance Increases



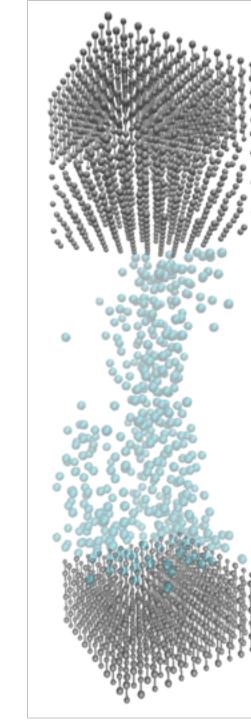
Current flow through HfO_x

Non-Filamentary



HfO_x : x = 1.512

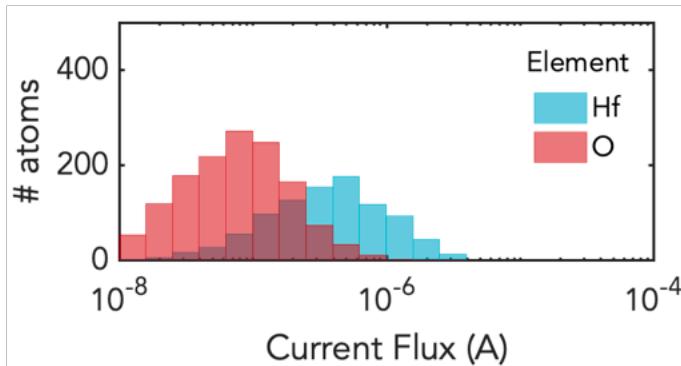
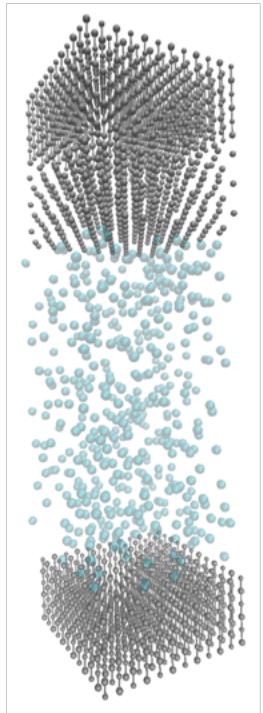
Filamentary



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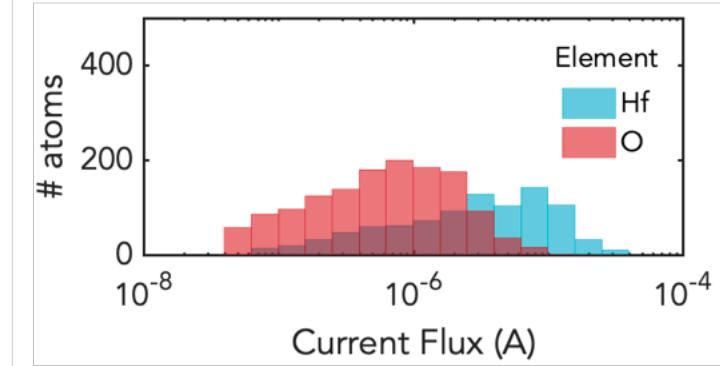
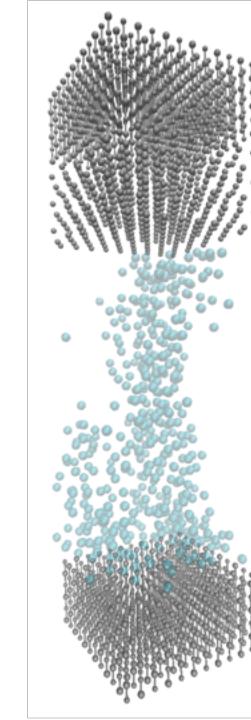
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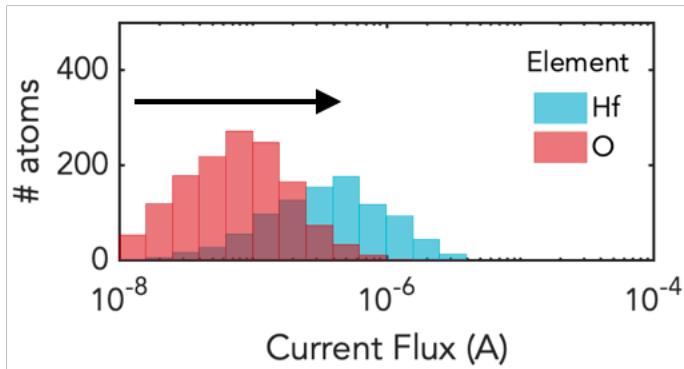
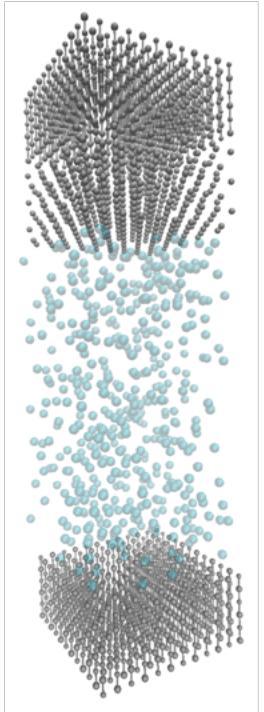
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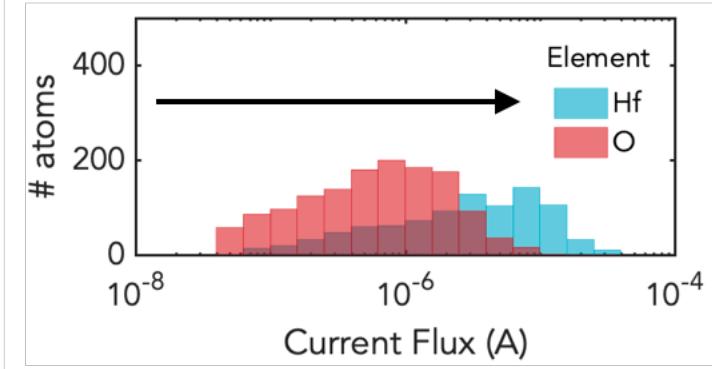
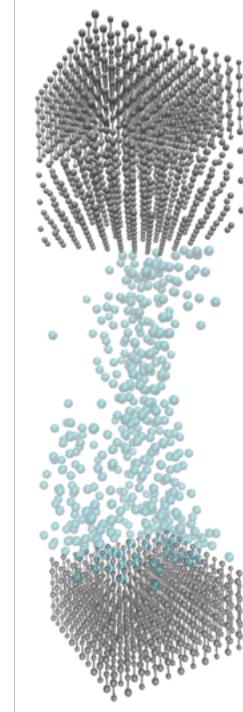
Current flow through HfO_x

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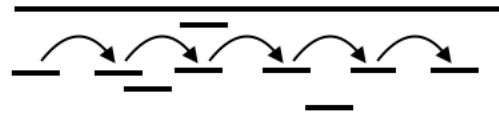
HfO_x : x = 1.512

Filamentary



HfO_x : x = 1.512

Conduction band



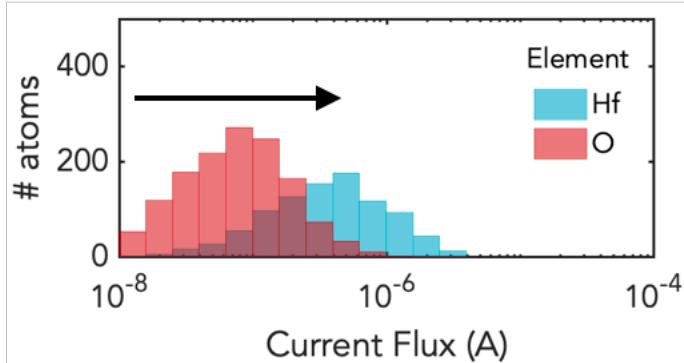
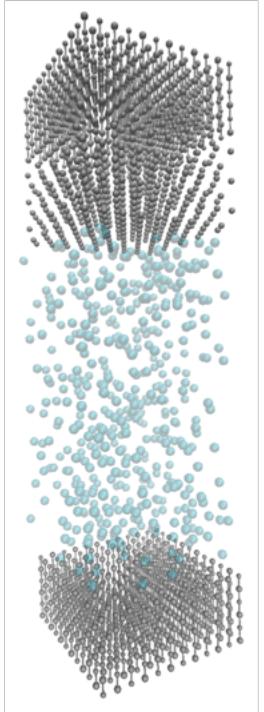
Conduction band



- The magnitude of current is increased in the presence of filamentary vacancy clusters

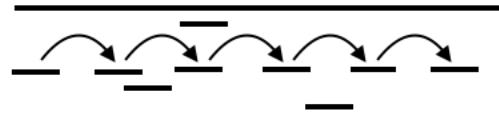
Current flow through HfO_x

Non-Filamentary

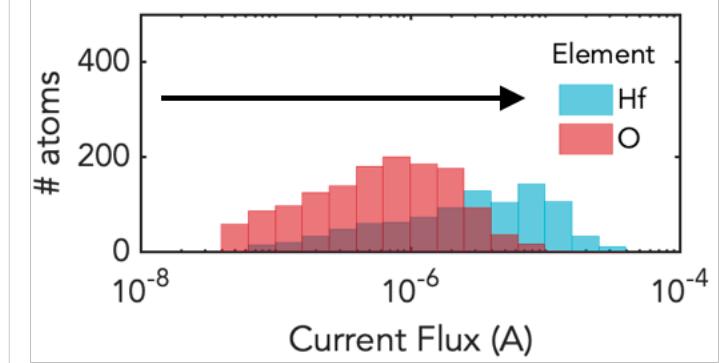
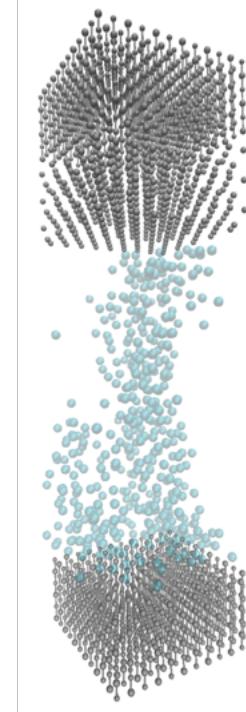


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Conduction band



Filamentary



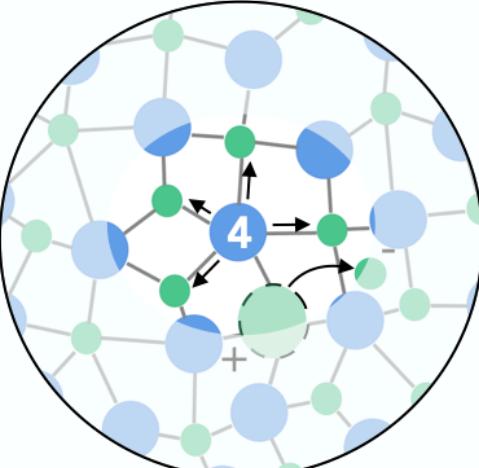
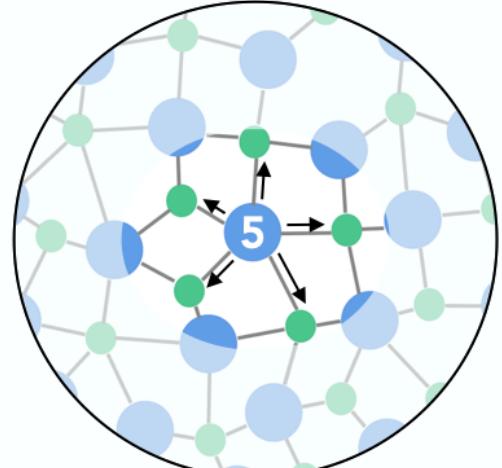
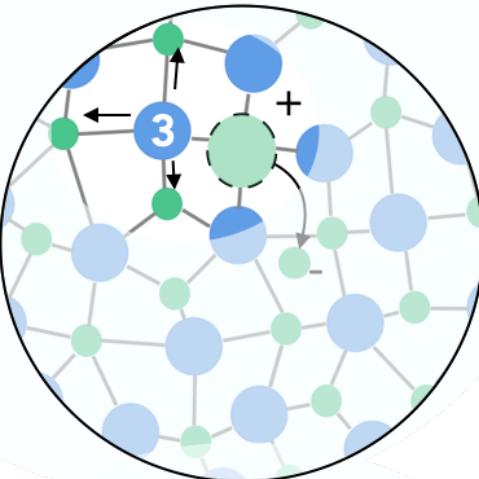
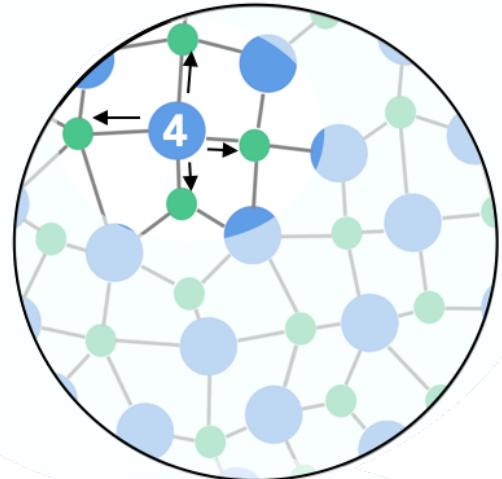
HfO_x : x = 1.512

Conduction band



- The magnitude of current is increased in the presence of filamentary vacancy clusters
- Current flows through Hf atoms

● Hf
● O
● + V_o
● - O^-

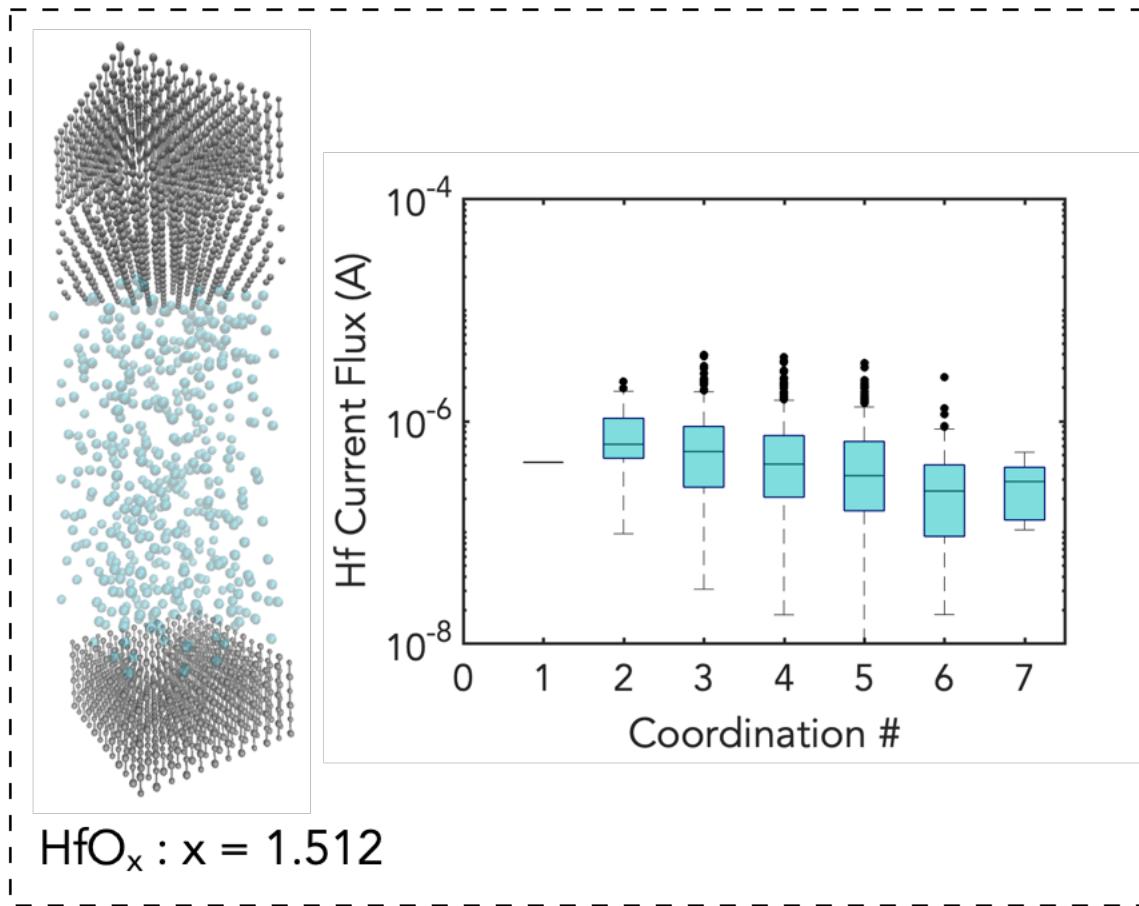


Oxygen coordination
is affected by...

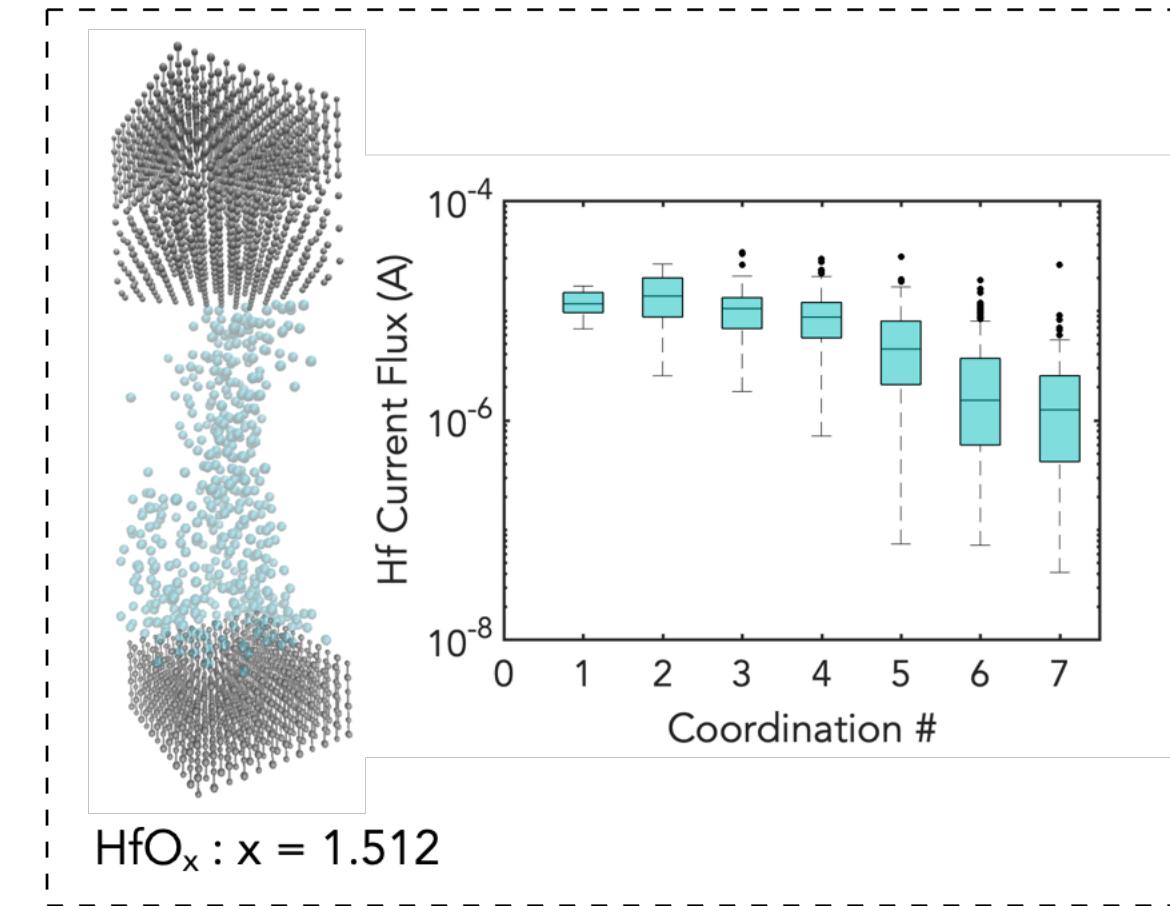
- Underlying atomic connectivity
- Presence of Oxygen vacancy defects

Current flow through the defective oxide

Non-Filamentary

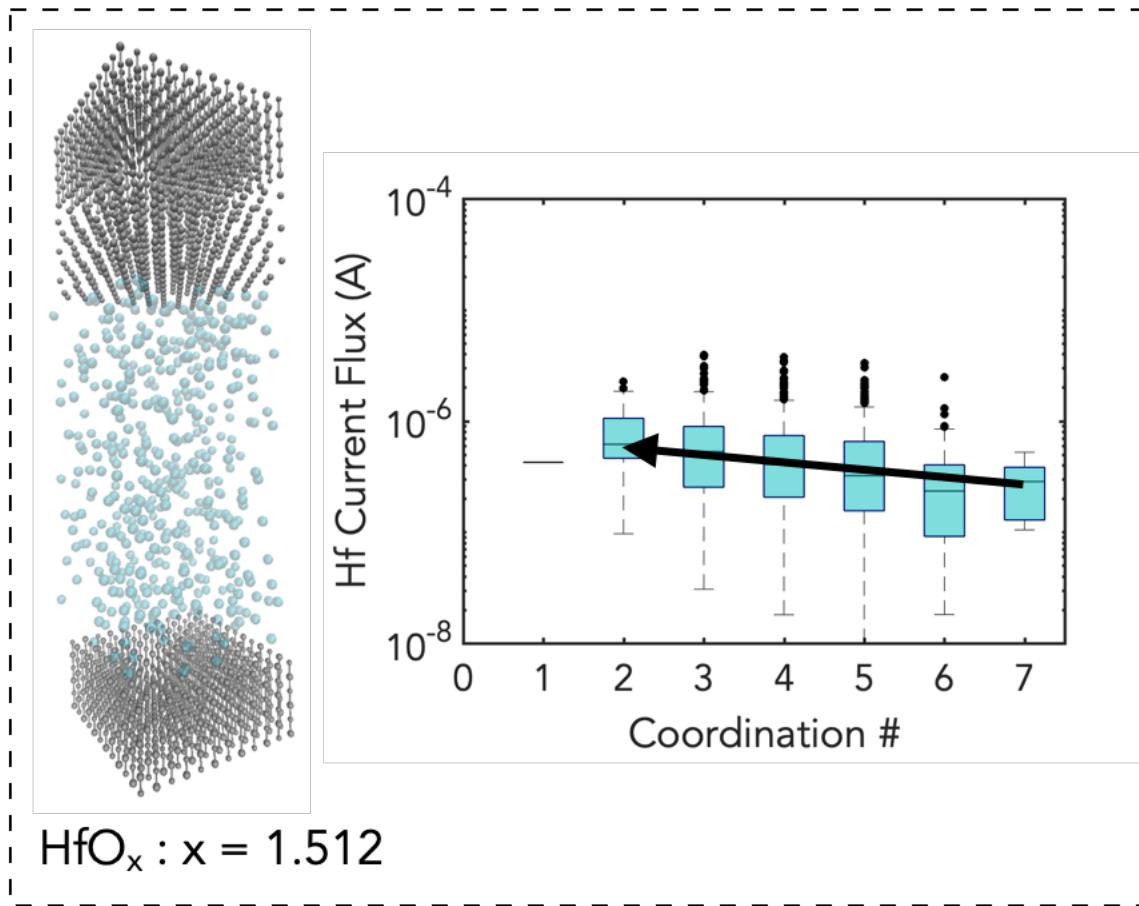


Filamentary

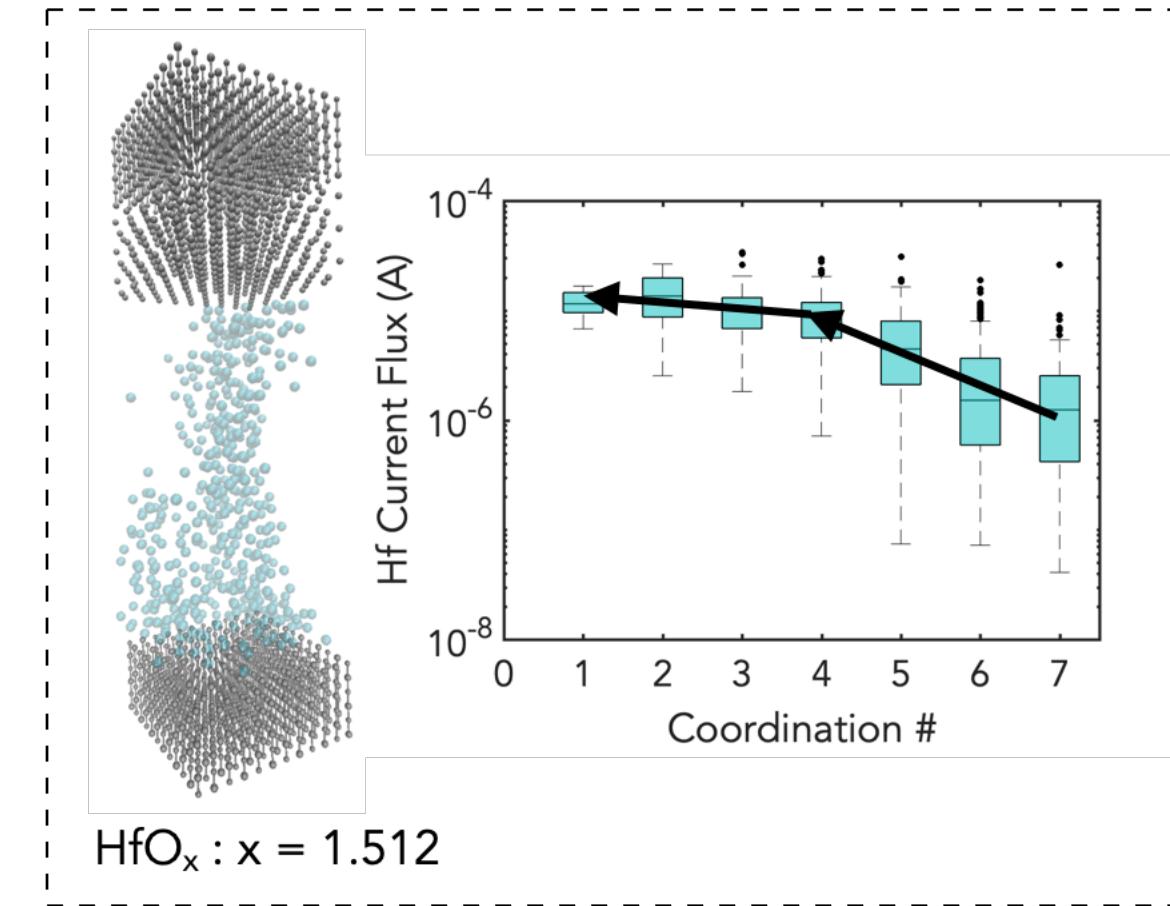


Current flow through the defective oxide

Non-Filamentary

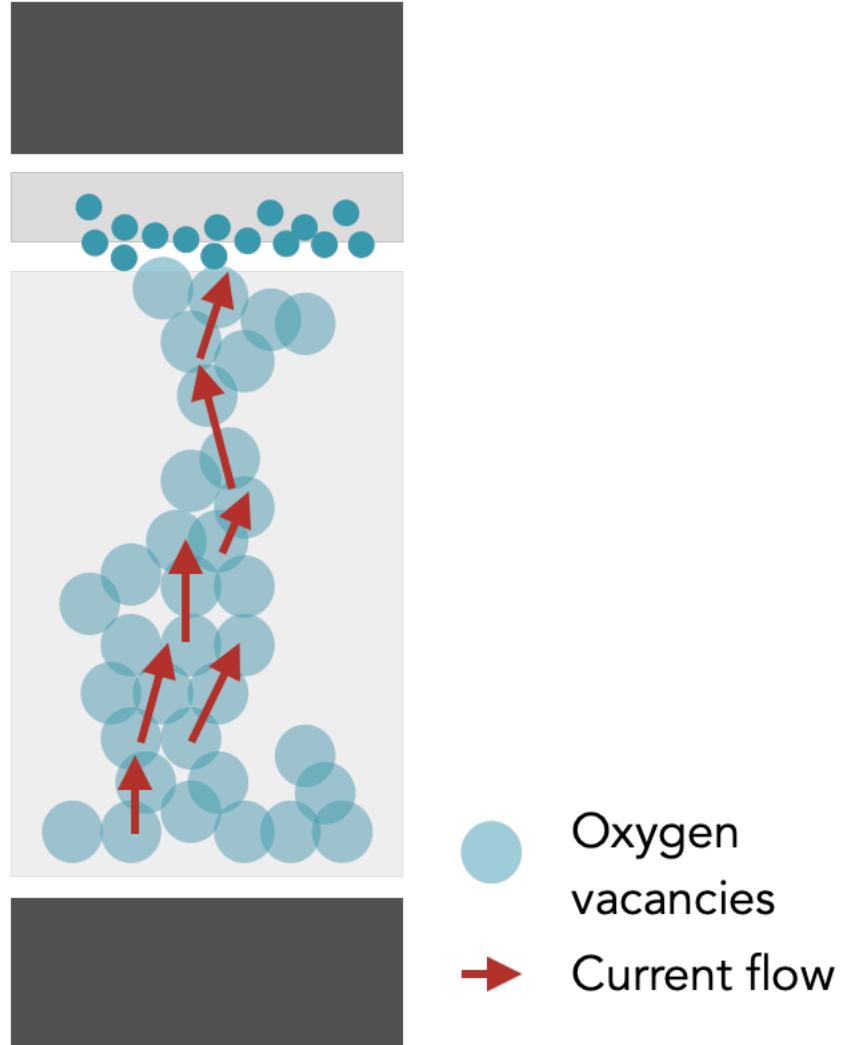


Filamentary



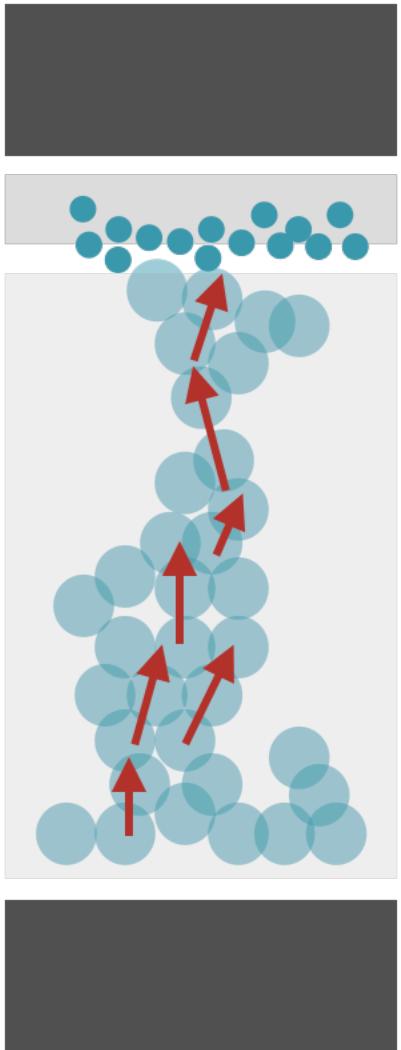
Summary

Some atoms direct
more of the
electronic current

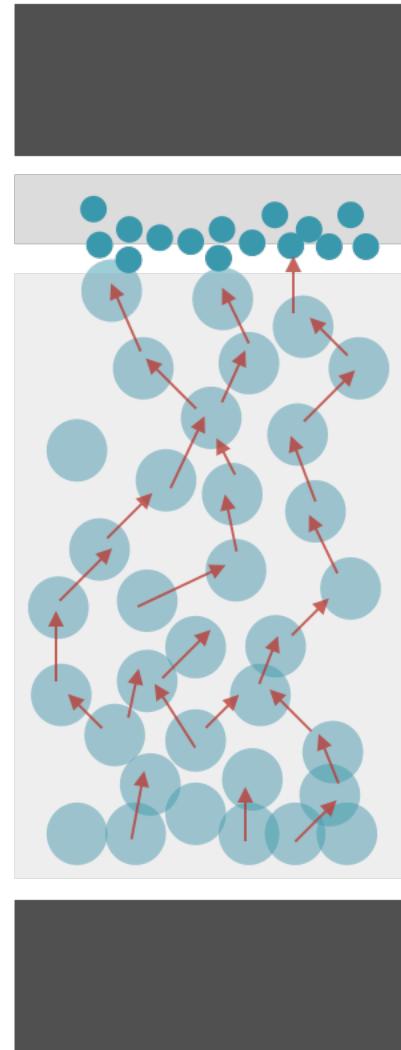


Summary

Some atoms direct
more of the
electronic current



Oxygen
vacancies
→ Current flow



Individual atoms
direct less of the
electronic current

Outlook: Methods to improve analog operation

Chemical/compositional

- Adding dopants/nucleation sites
- Engineered bilayers with interface-type switching

Thermal

- Thermal Enhancement Layers
- Optical pulses
- Operating at higher temperatures

Outlook: Methods to improve analog operation

Chemical/compositional

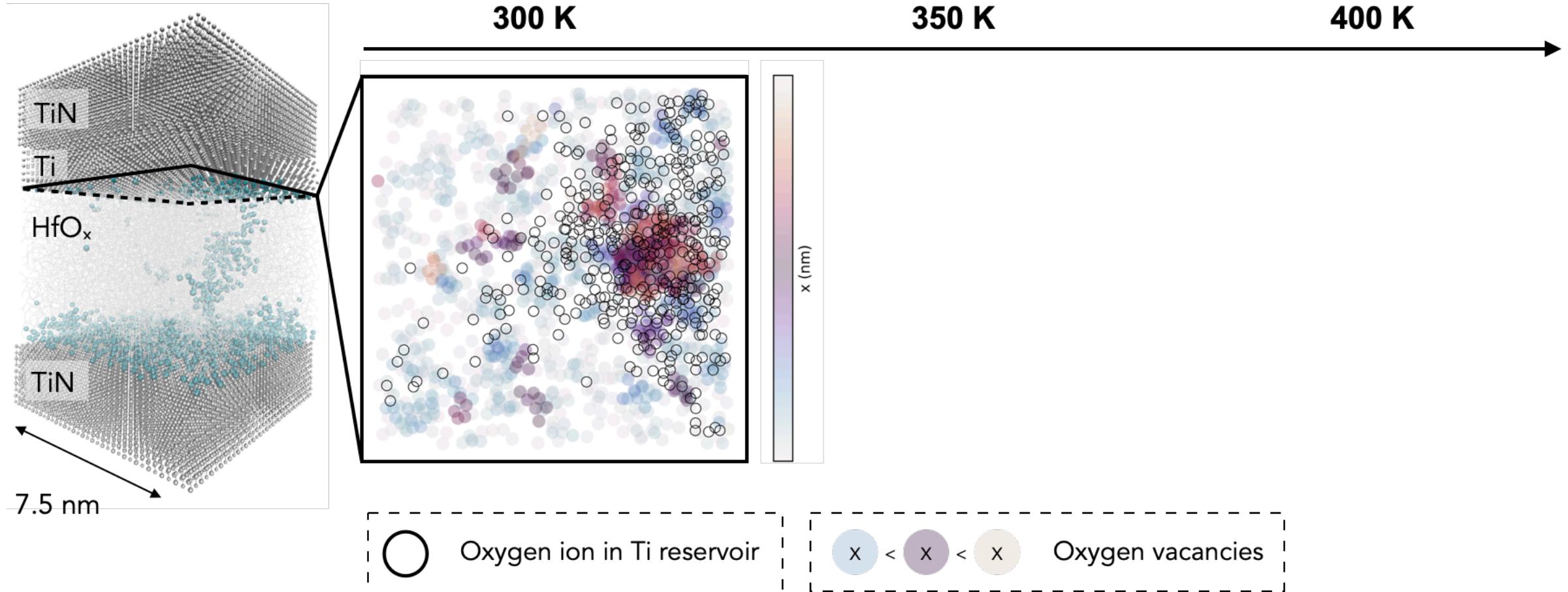
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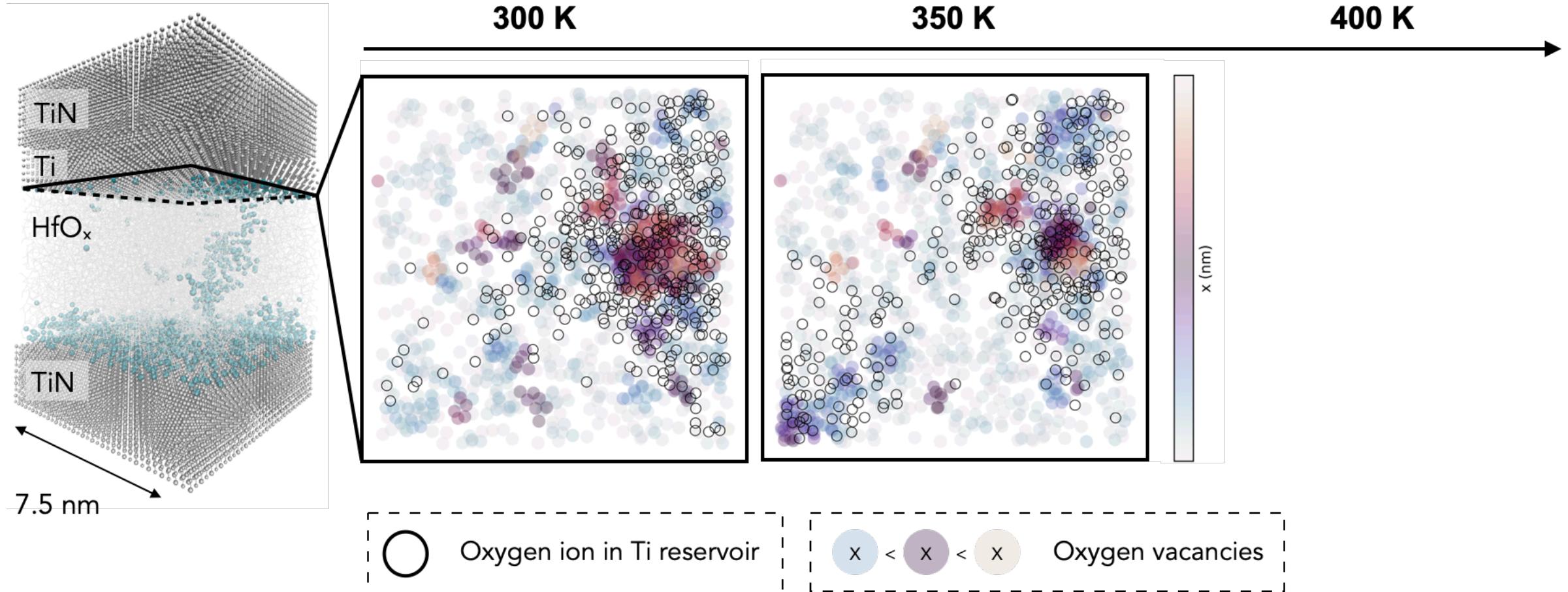
Outlook: Thermal engineering

Increasing electroforming temperature at fixed $V_{\text{FORM}} = 6.0 \text{ V}$



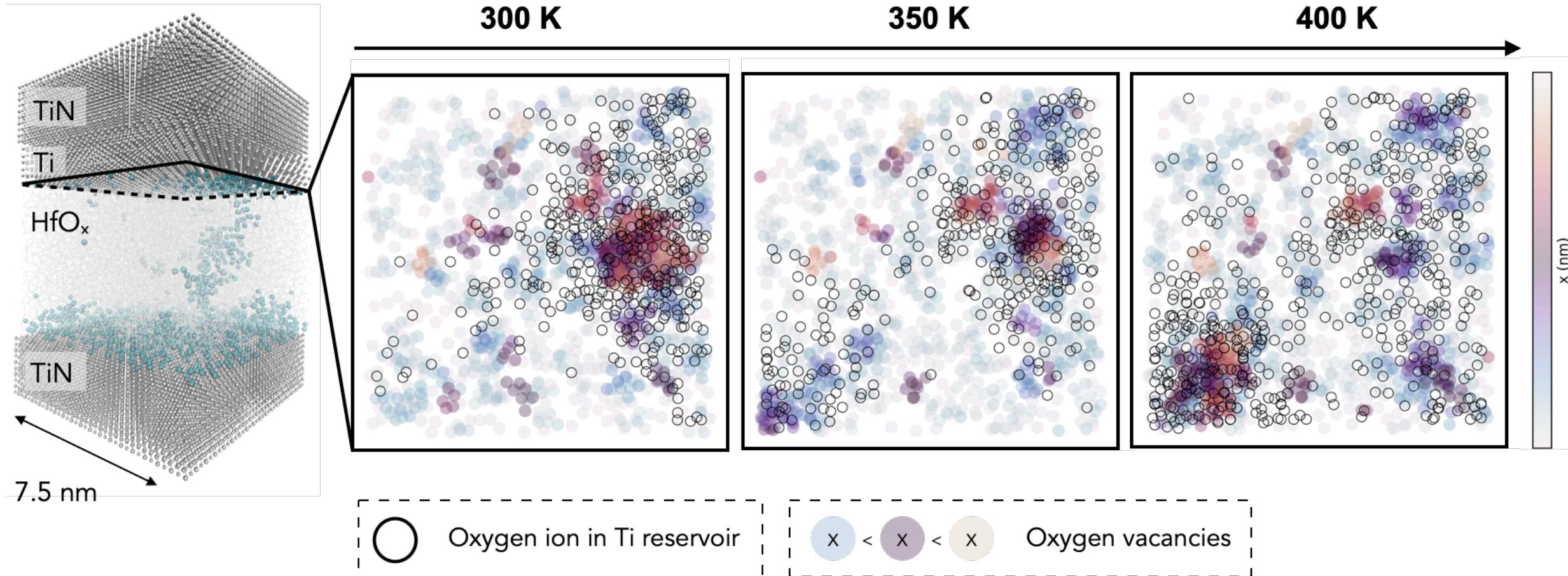
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Increasing electroforming temperature at fixed $V_{\text{FORM}} = 6.0 \text{ V}$



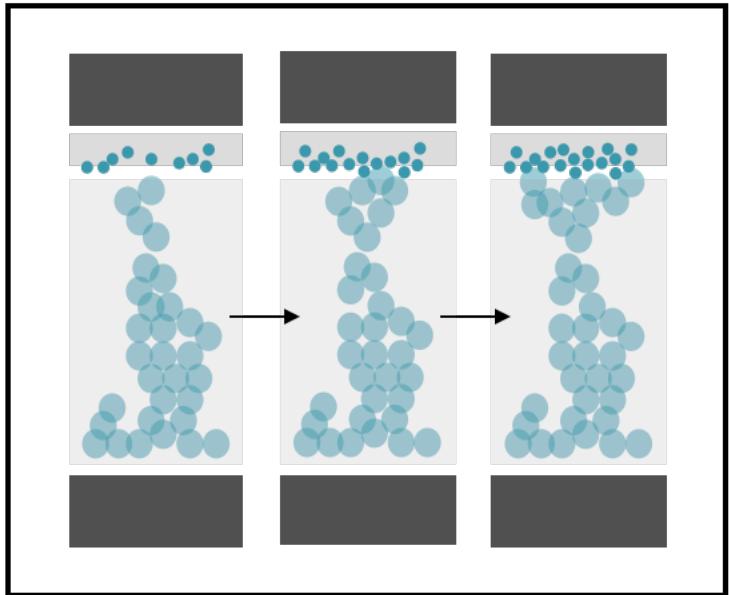
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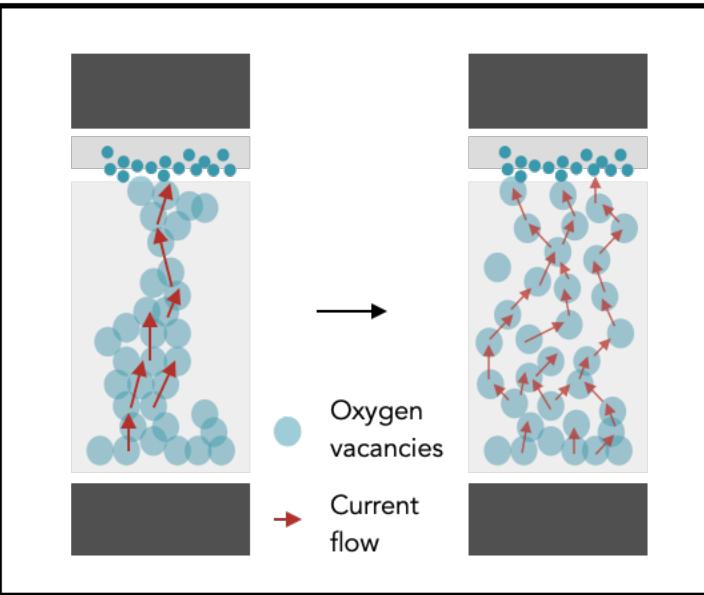


Summary and Acknowledgements

Origin of non-linear conductance updates

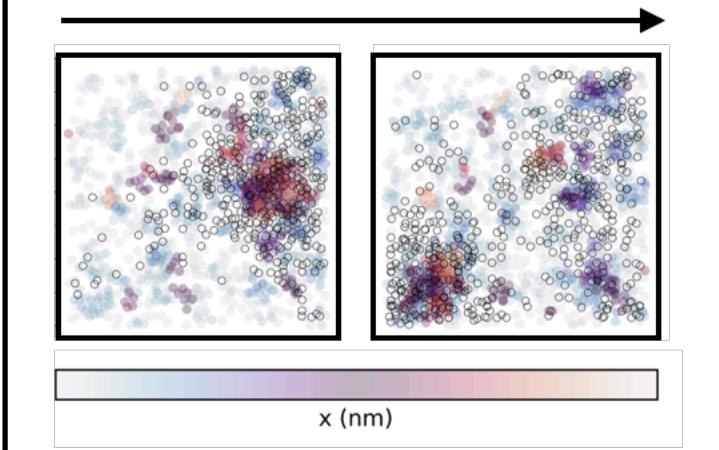


Coordination-dependance of current flow



Methods to achieve more uniformly defective oxides

Environment temperature during electroforming step



Discussions, moral support:

Marko Mladenović
Jente Clarysse
Kevin Portner
Mathieu Luisier

Computational Resources



CSCS

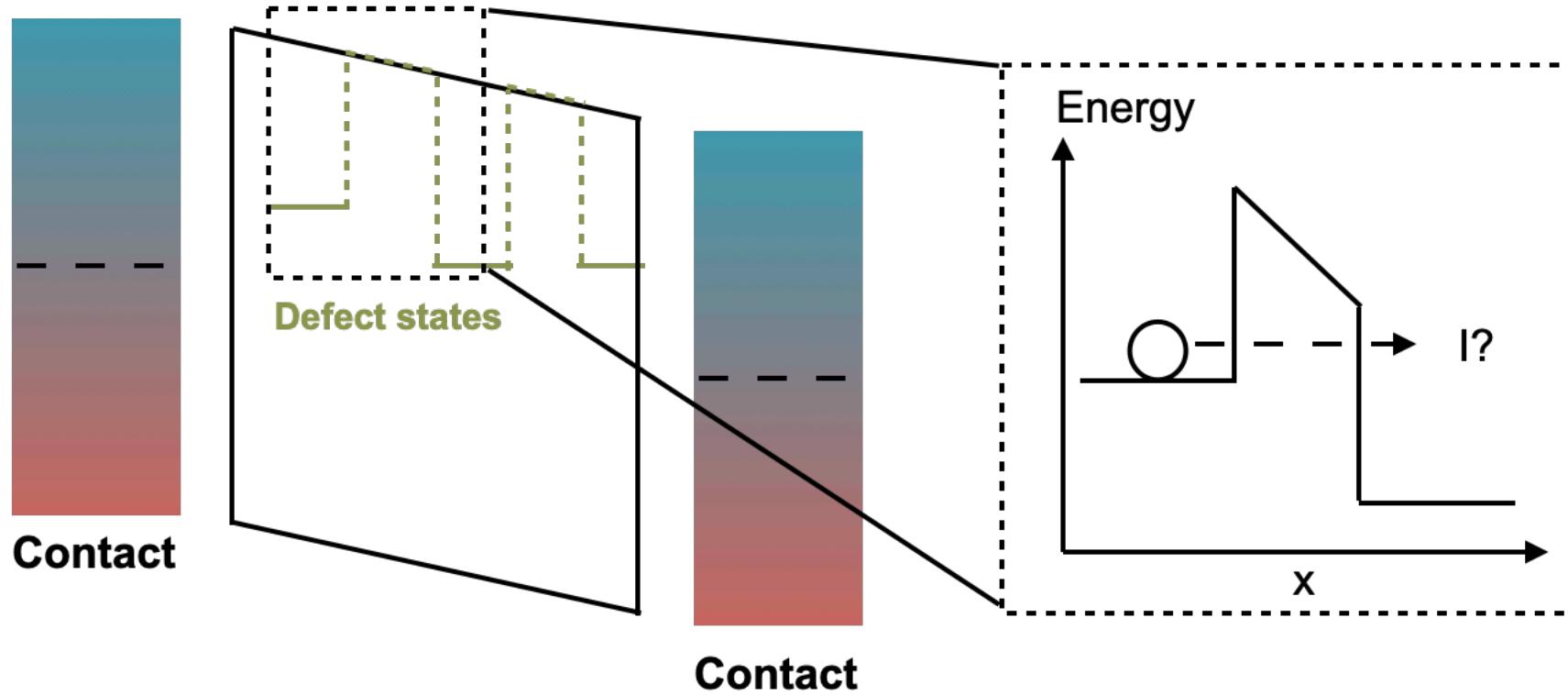
Funding



Swiss National
Science Foundation

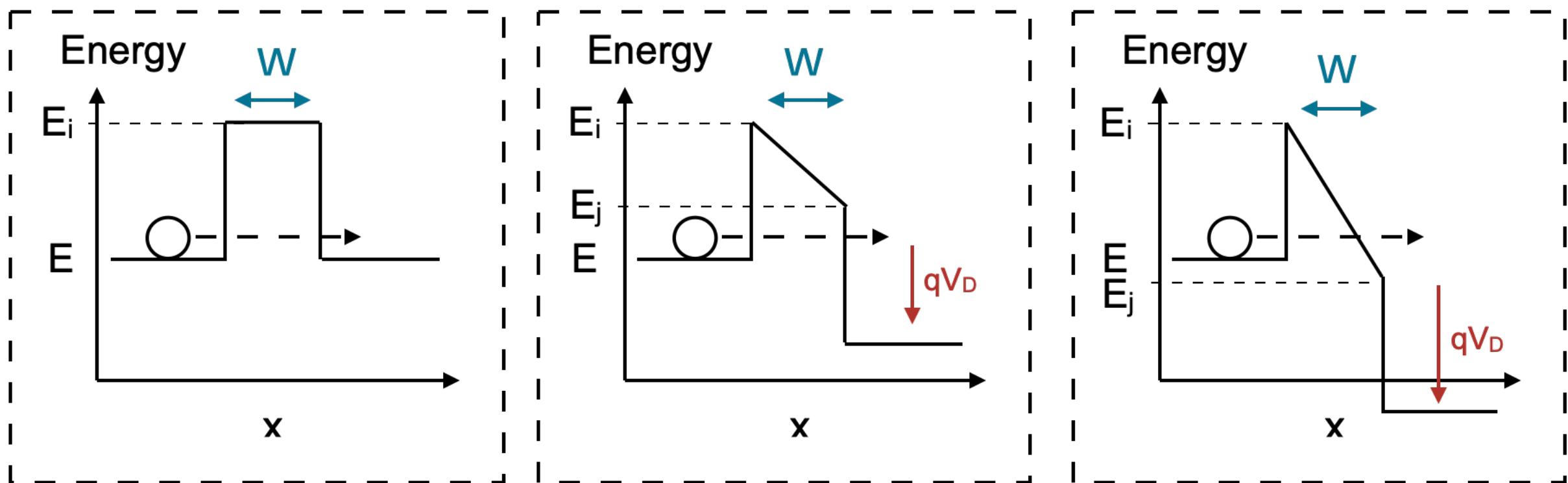


Mechanisms of Current Flow: Tunneling



$$T(E) = \exp(-\int Im(k(E)dx)) \quad \rightarrow \quad E = \frac{\hbar^2 k^2}{2m} \quad T(E) = \exp\left(-\frac{2m_e}{\hbar}\int \sqrt{E}dx\right)$$

Mechanisms of Current Flow: Tunneling



$$T(E) = \exp\left(-\frac{\sqrt{2m_e}}{\hbar} \cdot \sqrt{E_i \cdot W}\right)$$

$$T(E) = \exp\left(-\frac{\sqrt{2m_e}}{\hbar} \cdot \frac{2W}{3(E_i - E_j)} \cdot (E_i^{3/2} - E_j^{3/2})\right)$$

$$T(E) = \exp\left(-\frac{\sqrt{2m_e}}{\hbar} \cdot \frac{2W}{3(E_i - E_j)} \cdot E_i^{3/2}\right)$$